LAMPIRAN

LAMPIRAN A

Listing Program

```
$include(reg51.inc)

        org     00h                     ;vector interupsi motor
        ajmp    start

                VMotor      bit  p0.0    ;On Off Motor (0=off, 1=on)
                direction   bit  p0.1    ;arah putar motor (0=tutup, 1=buka)
                limitA      bit  p1.6    ;limit switch atas
                limitB      bit  p1.7    ;limit switch bawah
                vt          bit  p3.7    ;receive enable penerima
                danger      bit  p1.0    ;safety detector
                datatrima   equ  P2
----------------------------
; Program utama
----------------------------
start:
                jnb     vt,$            ;jika remote tidak aktif maka
                                        garasi tutup
bacadata:
                mov     A,datatrima
                cjne    A,#00000000b,cek2
                acall   tutup_garasi


cek2:
                cjne A,#00000101b,start
                acall buka_garasi
----------------------------
; Prosedur buka garasi
----------------------------

buka_garasi:
                setb    limitA          ;aktifkan internal pull-up port1.6
                nop
                nop                     ;tunggu 3µs
```

```
                nop
                jnb     limitA,buka         ;jika limit switch belum tertekan maka
                                             pintu garasi buka
                clr     Vmotor              ;jika limit switch tertekan matikan motor
                jmp     start               ;kembali kelabel start

;-------------------------------
;   prosedur tutup garasi
;-------------------------------

tutup_garasi:                               ;prosedur tutup garasi
                setb    danger              ;aktifkan internal pull-up port1.0
                nop
                nop                         ;tunggu 3µs
                nop
                jb      danger,allowed      ;jika detector tidak aktif maka tutup
                                             garasi
                clr     Vmotor              ;jika detector aktif(ada benda yang
                                             menghalangi)maka matikan motor
                jmp     start               ;lompat kelabel start

alowed:
                setb    limitB              ;aktifkan internal pull-up port1.7
                nop
                nop                         ;tunggu 3µs
                nop
                jnb     limitB,tutup        ;jika limit switch bawah belum tertekan
                                             maka tutup pintu garasi
                clr     Vmotor              ;jika limit switch bawah tertekan maka
                                             matikan motor
                jmp     start               ;lompat kelabel start

tutup:                                      ;prosedur tutup pintu garasi
                setb    Vmotor              ;hidupkan motor
                clr     direction           ;arahkan putaran motor kekiri(tutup)
                jmp     start               ;lompat kelabel start


;---------------------------------
;  prosedur buka pintu garasi
;---------------------------------

buka:                                       ;prosedur buka pintu garasi
```

```
        setb    Vmotor          ;hidupkan motor
        setb    direction       ;arahkan putaran motor kekanan(buka)
        jmp     start           ;lompat kelabel start
end                             ;akhir program
```

LAMPIRAN B

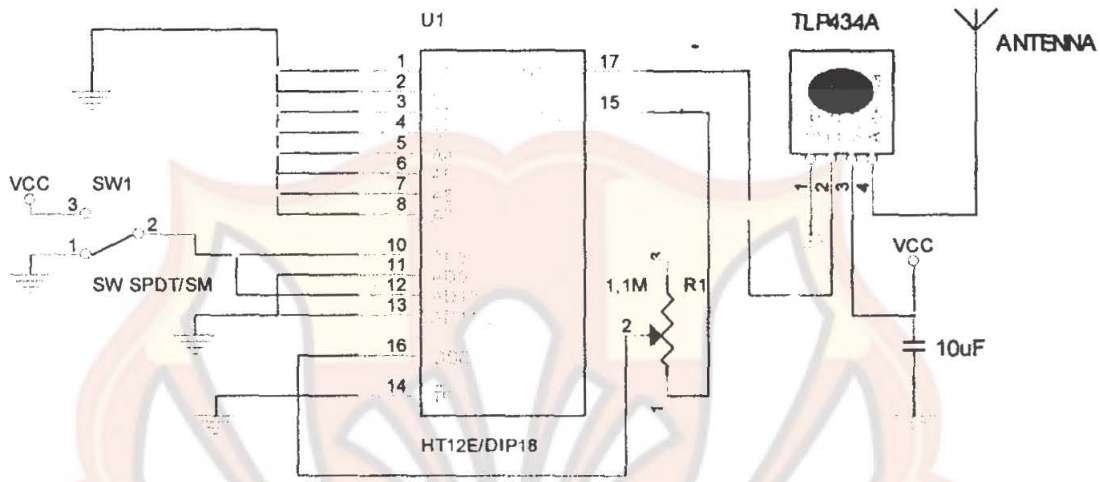
Gambar Alat

Bagian Garasi

Bagian Mobil (Pemancar)

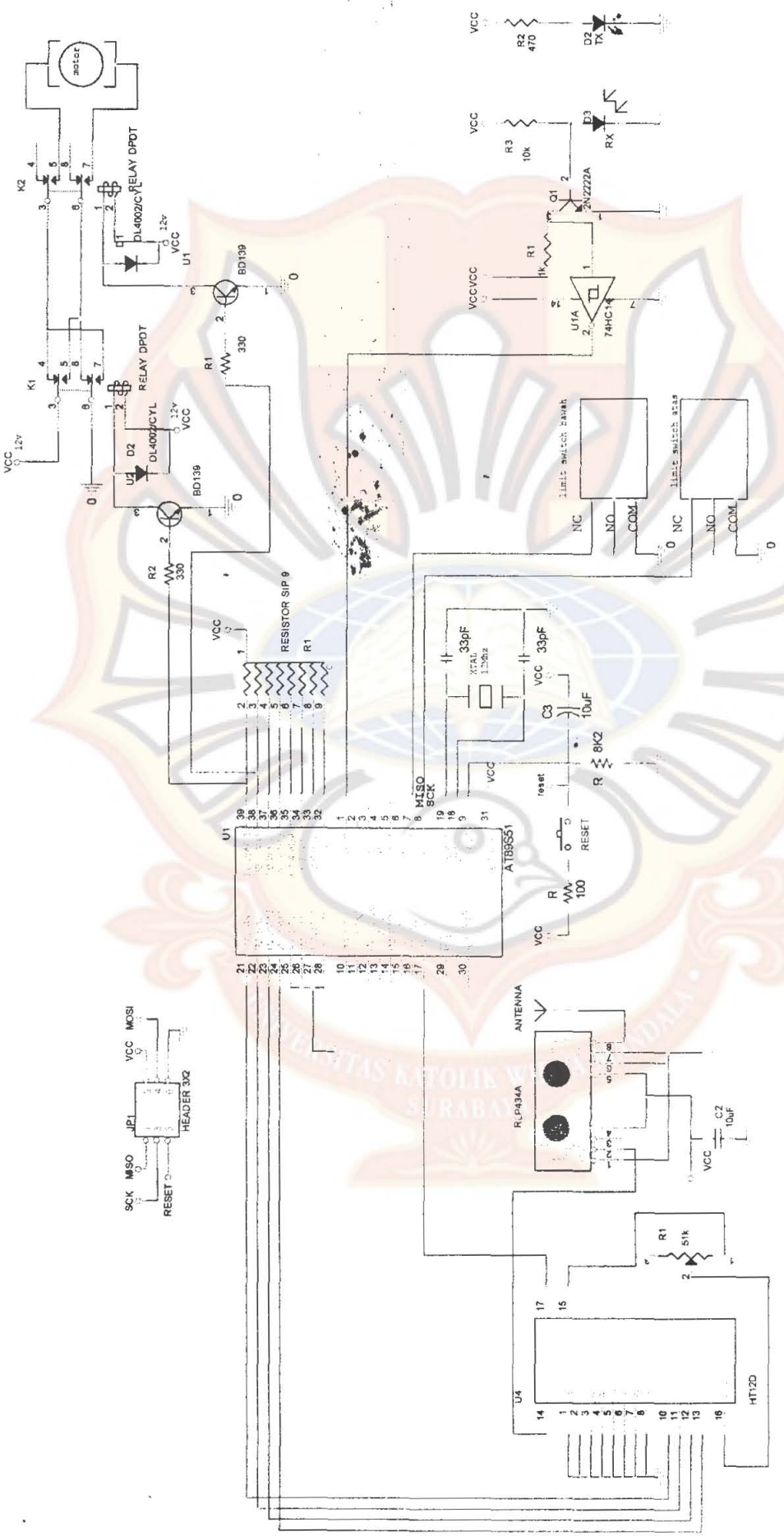
LAMPIRAN C

Gambar Rangkaian Pemancar



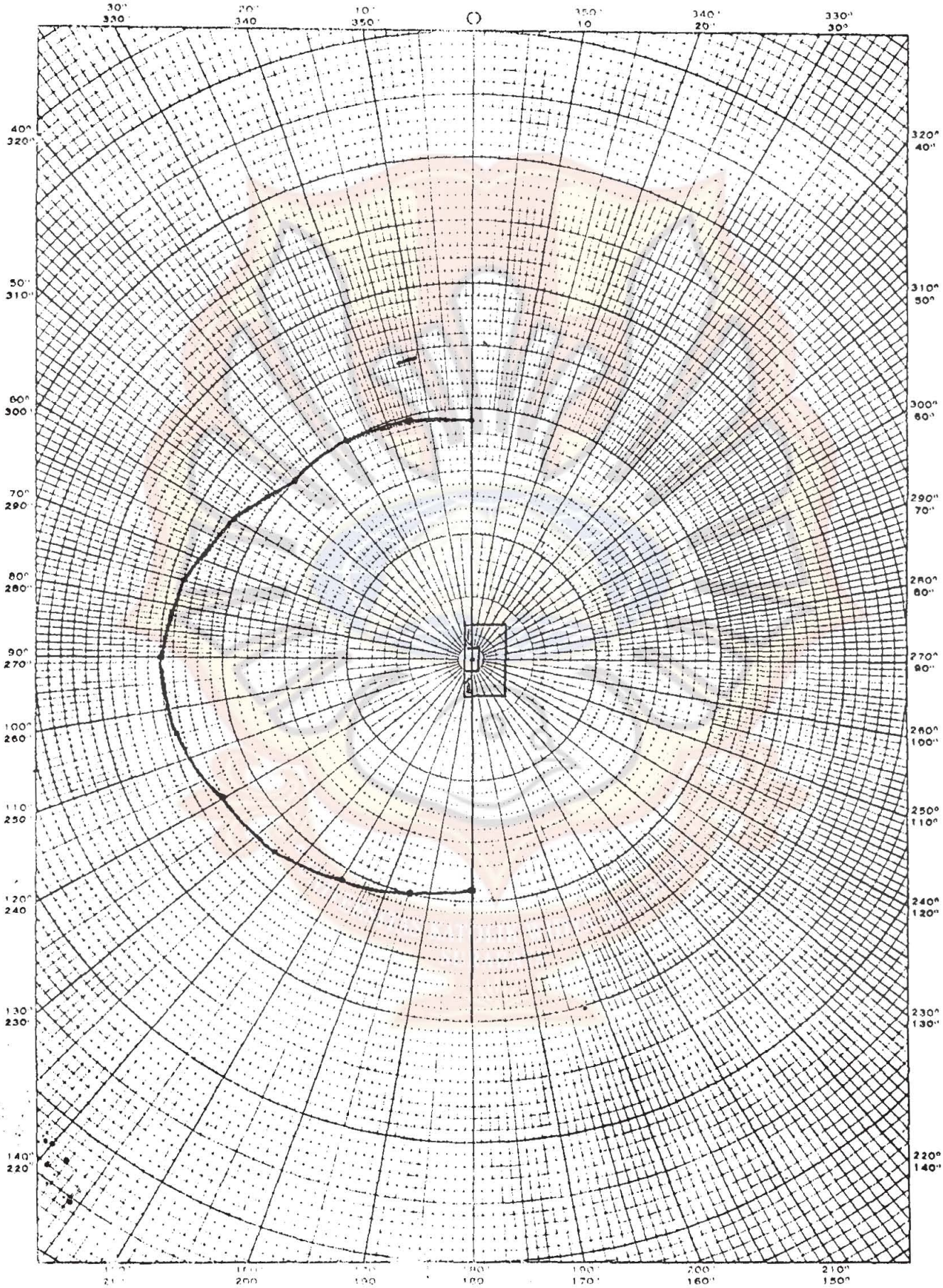
LAMPIRAN D

Gambar Rangkaian Penerima



LAMPIRAN E

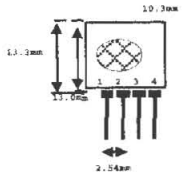
Polar Plot



LAMPIRAN F

Data Sheet

TLP434A Ultra Small Transmitter



pin 1 : GND
pin 2 : Data In
pin 3 : Vcc
pin 4 : Antenna (RF output)

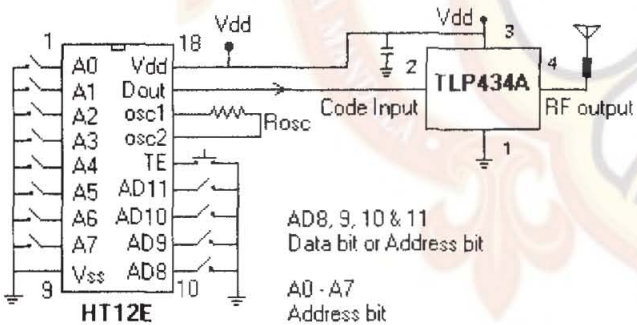
Frequency 315, 418 and 433.92 Mhz

***Modulation* : ASK**
Operation Voltage : 2 - 12 VDC

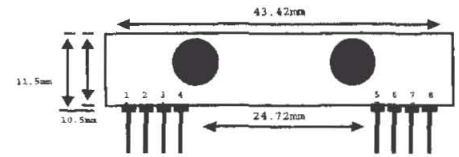
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Vcc	Operating supply voltage		2.0	-	12.0	V
Icc 1	Peak Current (2V)		-	-	1.64	mA
Icc 2	Peak Current (12V)		-	-	19.4	mA
Vh	Input High Voltage	Idata= 100uA (High)	Vcc-0.5	Vcc	Vcc+0.5	V
Vl	Input Low Voltage	Idata= 0 uA (Low)	-	-	0.3	V
FO	Absolute Frequency	315Mhz module	314.8	315	315.2	MHz
PO	RF Output Power- 50ohm	Vcc = 9V-12V	-	16	-	dBm
		Vcc = 5V-6V	-	14	-	dBm
DR	Data Rate	External Encoding	512	4.8K	200K	bps

Notes : (Case Temperature = 25°C +- 2°C , Test Load Impedance = 50 ohm)

Application Circuit :
Typical Key-chain Transmitter using HT12E-18DIP, a Binary 12 bit Encoder from Holtek Semiconductor Inc.



RLP434A SAW Based Receiver



pin 1 : Gnd
pin 2 : Digital Data Output
pin 3 : Linear Output /Test
pin 4 : Vcc
pin 5 : Vcc
pin 6 : Gnd
pin 7 : Gnd
pin 8 : Antenna

Frequency 315, 418 and 433.92 Mhz

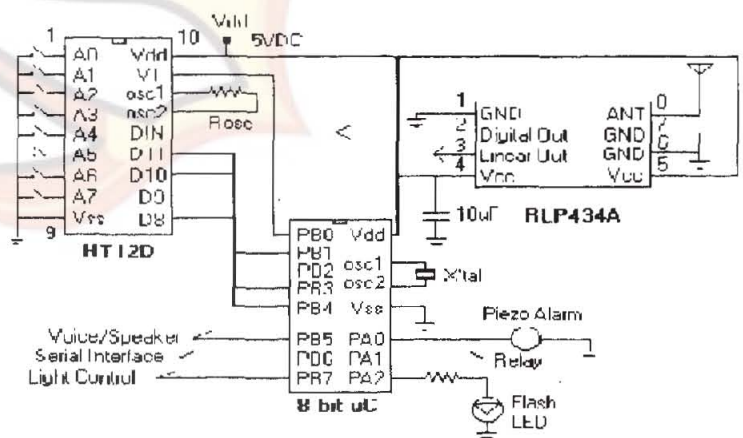
Modulation : ASK
Supply Voltage : 3.3 - 6.0 VDC
Output : Digital & Linear

Symbol	Parameter	Conditions	Min	Typ	Max	
Vcc	Operating supply voltage		3.3	5.0V	6.0	V
Itot	*Operating Current*		-	4.5		mA
Vdata	Data Out	Idata = +200 uA (High)	Vcc-0.5	-	Vcc	V
		Idata = -10 uA (Low)	-	-	0.3	V

Electrical Characteristics

Characteristics	SYM	Min	Typ	Max	Unit
Operation Radio Frequency	FC		315, 418 and 433.92		MHz
Sensitivity	Pref		-110		dBm
Channel Width			+-500		Khz
Noise Equivalent BW			4		Khz
Receiver Turn On Time			5		ms
Operation Temperature	Top	-20	-	80	C
Baseboard Data Rate			4.8		KHz

Application Circuit :
Typical RF Receiver using HT12D-18DIP, a Binary 12 bit Decoder with 8 bit uC HT48RXX from Holtek Semiconductor Inc.



Laipac Technology, Inc.
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LAIPAC
TECH

HT12A/HT12E
2^{12} Series of Encoders

Features

- Operating voltage
  - 2.4V~5V for the HT12A
  - 2.4V~12V for the HT12E
- Low power and high noise immunity CMOS technology
- Low standby current: 0.1μA (typ.) at V_{DD}=5V
- HT12A with a 38kHz carrier for infrared transmission medium
- Minimum transmission word
  - Four words for the HT12E
  - One word for the HT12A
- Built-in oscillator needs only 5% resistor
- Data code has positive polarity
- Minimal external components
- HT12A/E: 18-pin DIP/20-pin SOP package

Applications

- Burglar alarm system
- Smoke and fire alarm system
- Garage door controllers
- Car door controllers
- Car alarm system
- Security system
- Cordless telephones
- Other remote control systems

General Description

The 2^{12} encoders are a series of CMOS LSIs for remote control system applications. They are capable of encoding information which consists of N address bits and 12–N data bits. Each address/data input can be set to one of the two logic states. The programmed addresses/data are transmitted together with the header bits via an RF or an infrared transmission medium upon receipt of a trigger signal. The capability to select a $\overline{TE}$ trigger on the HT12E or a DATA trigger on the HT12A further enhances the application flexibility of the 2^{12} series of encoders. The HT12A additionally provides a 38kHz carrier for infrared systems.

Selection Table

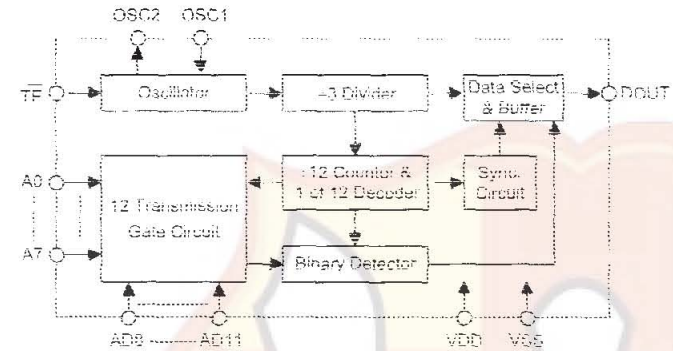
Function / Part No.	Address No.	Address/ Data No.	Data No.	Oscillator	Trigger	Package	Carrier Output	Negative Polarity
HT12A	8	0	4	455kHz resonator	D8~D11	18 DIP 20 SOP	38kHz	No
HT12E	8	4	0	RC oscillator	$\overline{TE}$	18 DIP 20 SOP	No	No

Note: Address/Data represents pins that can be address or data according to the decoder requirement.

Block Diagram

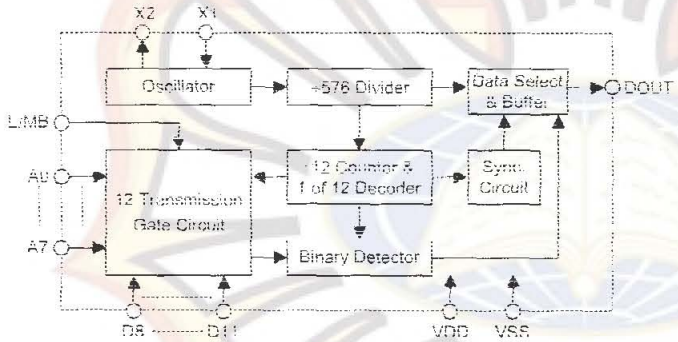
$\overline{TE}$ trigger

HT12E



DATA trigger

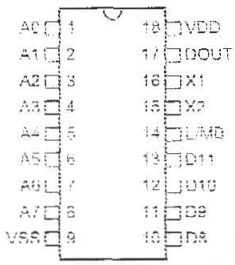
HT12A



Note: The address/data pins are available in various combinations (refer to the address/data table).

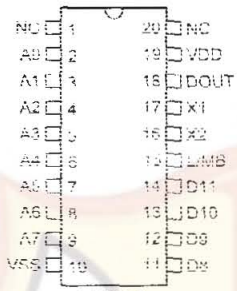
Pin Assignment

8-Address 4-Data



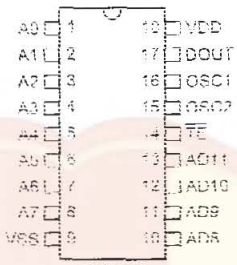
HT12A
– 18 DIP

8-Address 4-Data



HT12A
– 20 SOP

8-Address 4-Address/Data



HT12E
– 18 DIP

8-Address 4-Address/Data

HT12E
– 20 SOP

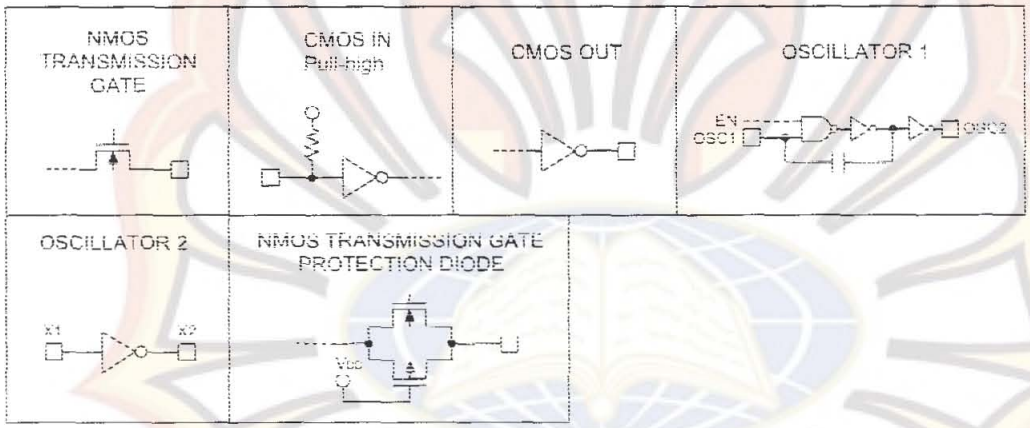
Pin Description

Pin Name	I/O	Internal Connection	Description
A0~A7	I	CMOS IN Pull-high (HT12A) NMOS TRANSMISSION GATE PROTECTION DIODE (HT12E)	Input pins for address A0~A7 setting These pins can be externally set to VSS or left open
AD8~AD11	I	NMOS TRANSMISSION GATE PROTECTION DIODE (HT12E)	Input pins for address/data AD8~AD11 setting These pins can be externally set to VSS or left open
D8~D11	I	CMOS IN Pull-high	Input pins for data D8~D11 setting and transmission enable, active low These pins should be externally set to VSS or left open (see Note)
DOUT	O	CMOS OUT	Encoder data serial transmission output
L/MB	I	CMOS IN Pull-high	Latch/Momentary transmission format selection pin. Latch: Floating or VDD Momentary: VSS

Pin Name	I/O	Internal Connection	Description
TE	I	CMOS IN Pull-high	Transmission enable, active low (see Note)
OSC1	I	OSCILLATOR 1	Oscillator input pin
OSC2	O	OSCILLATOR 1	Oscillator output pin
X1	I	OSCILLATOR 2	455kHz resonator oscillator input
X2	O	OSCILLATOR 2	455kHz resonator oscillator output
VSS	I	—	Negative power supply, grounds
VDD	I	—	Positive power supply

Note: D8~D11 are all data input and transmission enable pins of the HT12A.
$\overline{TE}$ is a transmission enable pin of the HT12E.

Approximate internal connections



Absolute Maximum Ratings

Supply Voltage (HT12A) ..... −0.3V to 5.5V
Input Voltage ..... V_{SS}−0.3 to V_{DD}+0.3V
Operating Temperature ..... −20°C to 75°C
Supply Voltage (HT12E) ..... 0.3V to 13V
Storage Temperature ..... −50°C to 125°C

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Electrical Characteristics

HT12A Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DD}	Operating Voltage	—	—	2.4	3	5	V
I_{STB}	Standby Current	3V	Oscillator stops	—	0.1	1	μA
		5V		—	0.1	1	μA
I_{DD}	Operating Current	3V	No load f_{OSC}=455kHz	—	200	400	μA
		5V		—	400	800	μA
I_{DOUT}	Output Drive Current	5V	V_{OH}=0.9V_{DD} (Source)	-1	-1.6	—	mA
			V_{OL}=0.1V_{DD} (Sink)	2	3.2	—	mA
V_{IH}	"H" Input Voltage	—	—	0.8V_{DD}	—	V_{DD}	V
V_{IL}	"L" Input Voltage	—	—	0	—	0.2V_{DD}	V
R_{DATA}	D8~D11 Pull-high Resistance	5V	V_{DATA}=0V		150	300	kΩ

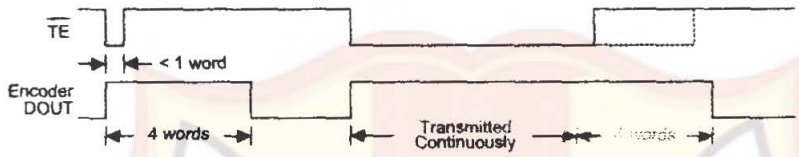
HT12E Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DD}	Operating Voltage	—	—	2.4	5	12	V
I_{STB}	Standby Current	3V	Oscillator stops	—	0.1	1	μA
		12V		—	2	4	μA
I_{DD}	Operating Current	3V	No load f_{OSC}=3kHz	—	40	80	μA
		12V		—	150	300	μA
I_{DOUT}	Output Drive Current	5V	V_{OH}=0.9V_{DD} (Source)	-1	-1.6	—	mA
			V_{OL}=0.1V_{DD} (Sink)	1	1.6	—	mA
V_{IH}	"H" Input Voltage	—	—	0.8V_{DD}	—	V_{DD}	V
V_{IL}	"L" Input Voltage	—	—	0	—	0.2V_{DD}	V
f_{OSC}	Oscillator Frequency	5V	R_{OSC}=1.1MΩ	—	3	—	kHz
$R_{\overline{TE}}$	$\overline{TE}$ Pull-high Resistance	5V	$V_{\overline{TE}}$=0V	—	1.5	3	MΩ

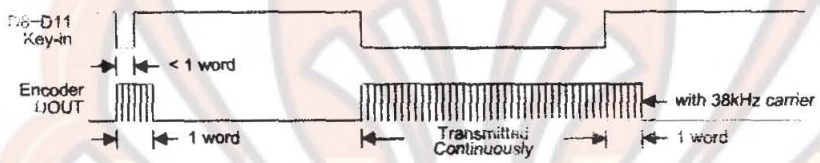
Functional Description

Operation

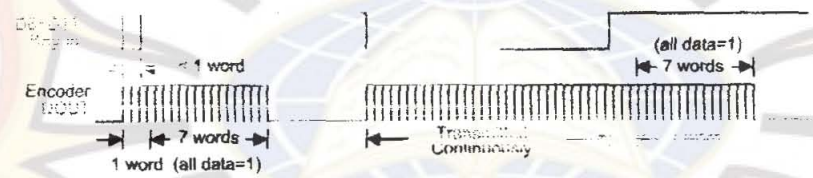
The 2^{12} series of encoders begin a 4-word transmission cycle upon receipt of a transmission enable ($\overline{TE}$ for the HT12E or D8~D11 for the HT12A, active low). This cycle will repeat as long as the transmission enable ($\overline{TE}$ or D8~D11) is held low. Once the transmission enable returns high the encoder output completes its final cycle and then stops as shown below.



Transmission timing for the HT12E



Transmission timing for the HT12A (L/M8=Floating or VDD)

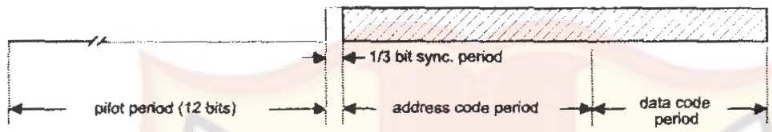


Transmission timing for the HT12A (L/M8=VSS)

Information word

If L/MB=1 the device is in the latch mode (for use with the latch type of data decoders). When the transmission enable is removed during a transmission, the DOUT pin outputs a complete word and then stops. On the other hand, if L/MB=0 the device is in the momentary mode (for use with the momentary type of data decoders). When the transmission enable is removed during a transmission, the DOUT outputs a complete word and then adds 7 words all with the "1" data code.

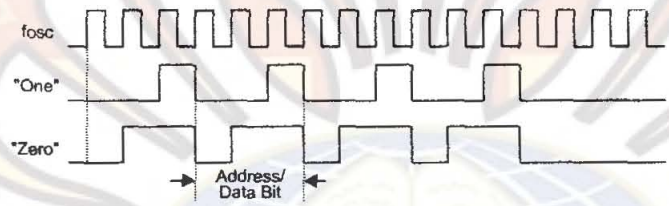
An information word consists of 4 periods as illustrated below.



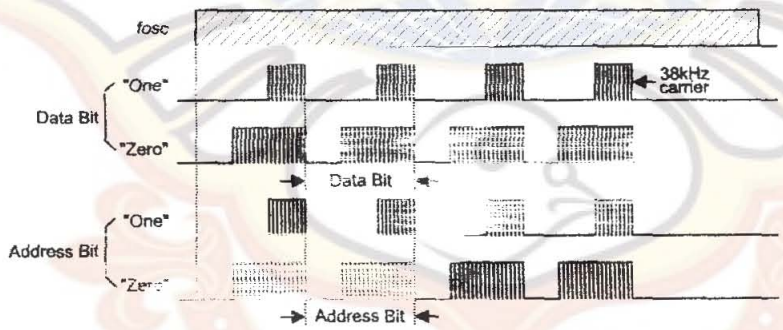
Composition of information

Address/data waveform

Each programmable address/data pin can be externally set to one of the following two logic states as shown below.



Address/Data bit waveform for the HT12E



Address/Data bit waveform for the HT12A

The address/data bits of the HT12A are transmitted with a 38kHz carrier for infrared remote controller flexibility.

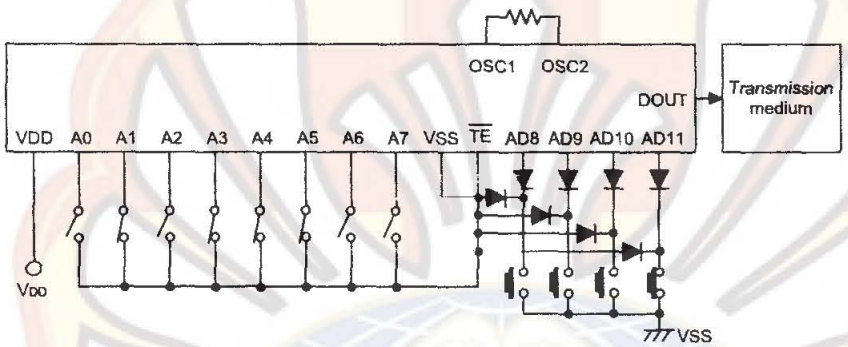
Address/data programming (preset)

The status of each address/data pin can be individually pre-set to logic "high" or "low". If a transmission-enable signal is applied, the encoder scans and transmits the status of the 12 bits of address/data serially in the order A0 to AD11 for the HT12E encoder and A0 to D11 for the HT12A encoder.

During information transmission these bits are transmitted with a preceding synchronization bit. If the trigger signal is not applied, the chip enters the standby mode and consumes a reduced current of less than 1μA for a supply voltage of 5V.

Usual applications preset the address pins with individual security codes using DIP switches or PCB wiring, while the data is selected by push buttons or electronic switches.

The following figure shows an application using the HT12E:



The transmitted information is as shown:

Pilot & Sync.	A0	A1	A2	A3	A4	A5	A6	A7	AD8	AD9	AD10	AD11
	1	0	1	0	0	0	1	1	1	1	1	0

Address/Data sequence

The following provides the address/data sequence table for various models of the 2^{12} series of encoders. The correct device should be selected according to the individual address and data requirements.

Part No.	Address/Data Bits											
	0	1	2	3	4	5	6	7	8	9	10	11
HT12A	A0	A1	A2	A3	A4	A5	A6	A7	D8	D9	D10	D11
HT12E	A0	A1	A2	A3	A4	A5	A6	A7	AD8	AD9	AD10	AD11

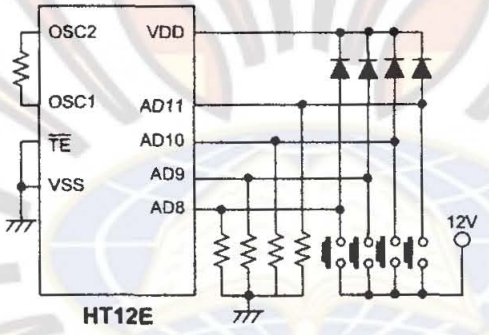
Transmission enable

For the HT12E encoders, transmission is enabled by applying a low signal to the $\overline{TE}$ pin. For the HT12A encoders, transmission is enabled by applying a low signal to one of the data pins D8~D11.

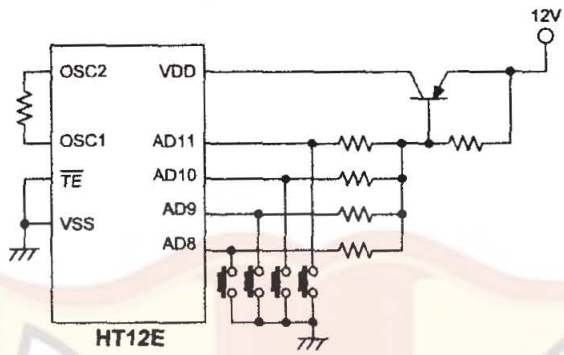
Two erroneous HT12E application circuits

The HT12E must follow closely the application circuits provided by Holtek (see the "Application circuits").

- Error: AD8~AD11 pins input voltage > V_{DD}+0.3V

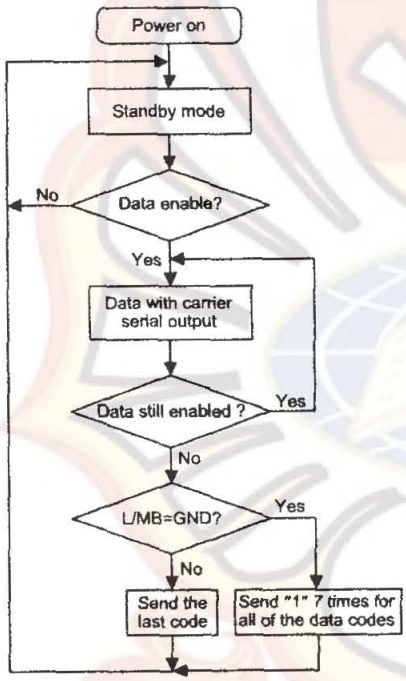


• Error: The IC's power source is activated by pins AD8~AD11

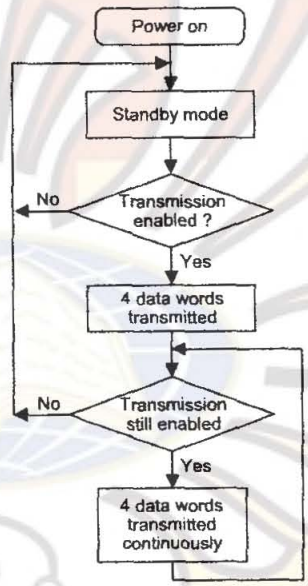


Flowchart

• HT12A

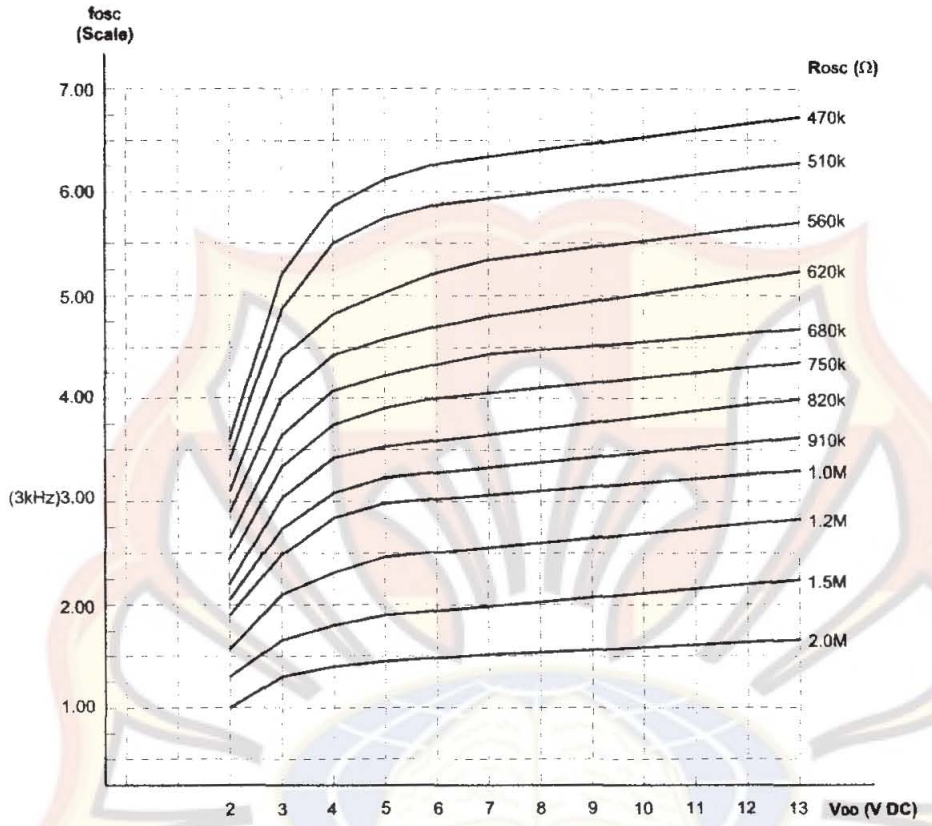


• HT12E



Note: D8~D11 are transmission enables of the HT12A.
$\overline{TE}$ is the transmission enable of the HT12E.

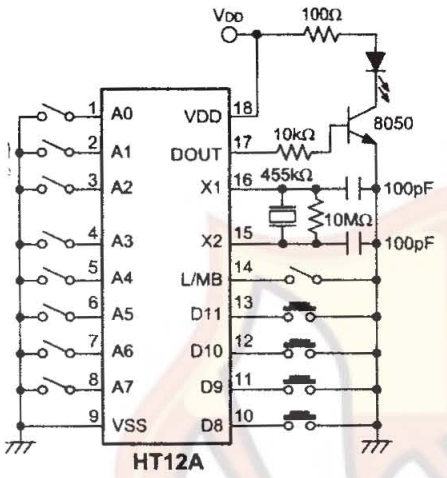
Oscillator frequency vs supply voltage

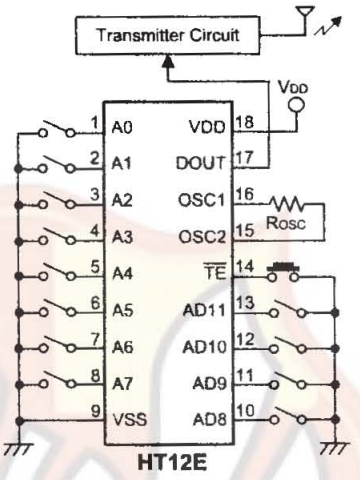


The recommended oscillator frequency is f_{OSCD} (decoder) $\cong 50\ f_{OSCE}$ (HT12E encoder)

$\cong \frac{1}{3} f_{OSCE}$ (HT12A encoder)

Application Circuits





Note: Typical infrared diode: EL-1L2 (KODENSHI CORP.)
Typical RF transmitter: JR-220 (JUWA CORP.)

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HOLTEK

2^{12} Series of Decoders

Features

- Operating voltage: 2.4V~12V
- Low power and high noise immunity CMOS technology
- Low standby current
- Capable of decoding 12 bits of information
- Pair with Holtek's 2^{12} series of encoders
- Binary address setting
- Received codes are checked 3 times
- Address/Data number combination
  HT12D: 8 address bits and 4 data bits
  HT12F: 12 address bits only
- Built-in oscillator needs only 5% resistor
- Valid transmission indicator
- Easy interface with an RF or an infrared transmission medium
- Minimal external components

Applications

- Burglar alarm system
- Smoke and fire alarm system
- Garage door controllers
- Car door controllers
- Car alarm system
- Security system
- Cordless telephones
- Other remote control systems

General Description

The 2^{12} decoders are a series of CMOS LSIs for remote control system applications. They are paired with Holtek's 2^{12} series of encoders (refer to the encoder/decoder cross reference table). For proper operation, a pair of encoder/decoder with the same number of addresses and data format should be chosen.

The decoders receive serial addresses and data from a programmed 2^{12} series of encoders that are transmitted by a carrier using an RF or an IR transmission medium. They compare the serial input data three times continuously with their local addresses. If no error or unmatched codes are found, the input data codes are decoded and then transferred to the output pins. The VT pin also goes high to indicate a valid transmission.

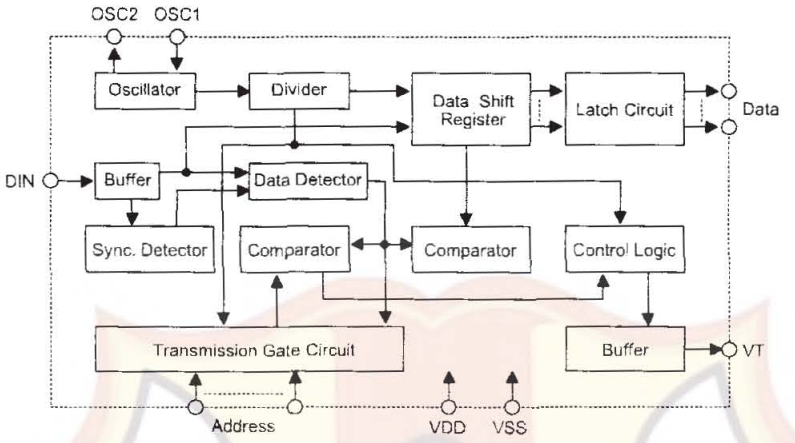
The 2^{12} series of decoders are capable of decoding informations that consist of N bits of address and 12–N bits of data. Of this series, the HT12D is arranged to provide 8 address bits and 4 data bits, and HT12F is used to decode 12 bits of address information.

Selection Table

Function / Part No.	Address No.	Data No.	Data Type	VT	Oscillator	Trigger	Package
HT12D	8	4	L	√	RC oscillator	DIN active "Hi"	18 DIP/20 SOP
HT12F	12	0	—	√	RC oscillator	DIN active "Hi"	18 DIP/20 SOP

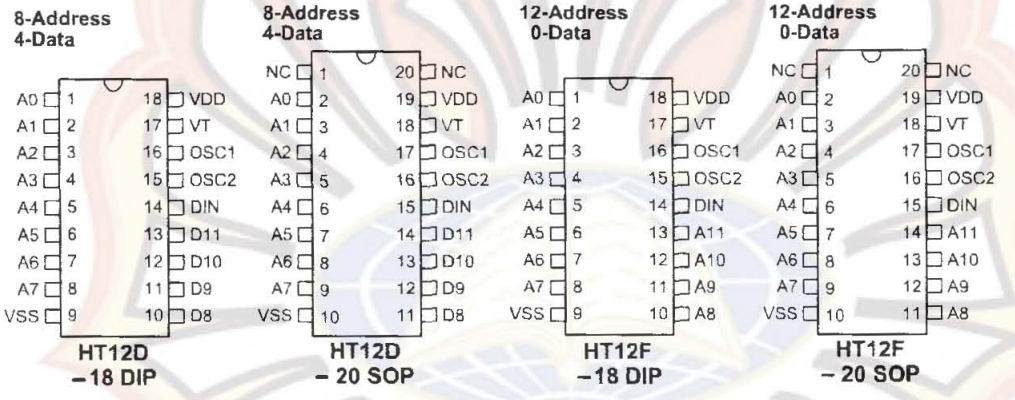
Notes: Data type: L stands for latch type data output.
VT can be used as a momentary data output.

Block Diagram



Note: The address/data pins are available in various combinations (see the address/data table).

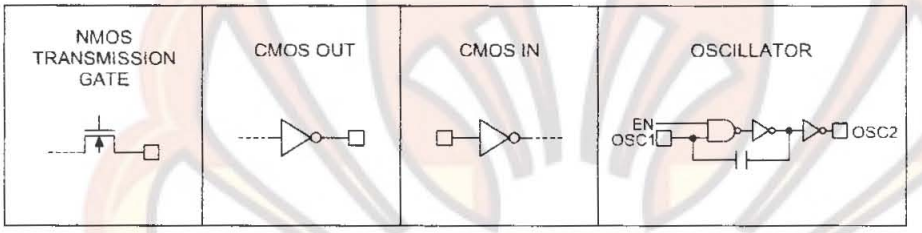
Pin Assignment



Pin Description

Pin Name	I/O	Internal Connection	Description
A0~A11	I	NMOS TRANSMISSION GATE	Input pins for address A0~A11 setting They can be externally set to VDD or VSS.
D8~D11	O	CMOS OUT	Output data pins
DIN	I	CMOS IN	Serial data input pin
VT	O	CMOS OUT	Valid transmission, active high
OSC1	I	OSCILLATOR	Oscillator input pin
OSC2	O	OSCILLATOR	Oscillator output pin
VSS	I	—	Negative power supply (GND)
VDD	I	—	Positive power supply

Approximate internal connection circuits



Absolute Maximum Ratings

Supply Voltage.....–0.3V to 13V
Input Voltage.....V_{SS}–0.3 to V_{DD}+0.3V
Storage Temperature.....–50°C to 125°C
Operating Temperature .....–20°C to 75°C

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Electrical Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DD}	Operating Voltage	—	—	2.4	5	12	V
I_{STB}	Standby Current	5V	Oscillator stops	—	0.1	1	μA
		12V		—	2	4	μA
I_{DD}	Operating Current	5V	No load f_{OSC}=150kHz	—	200	400	μA
I_O	Data Output Source Current (D8~D11)	5V	V_{OH}=4.5V	-1	-1.6	—	mA
	Data Output Sink Current (D8~D11)	5V	V_{OL}=0.5V	1	1.6	—	mA
I_{VT}	VT Output Source Current	5V	V_{OH}=4.5V	-1	-1.6	—	mA
	VT Output Sink Current		V_{OL}=0.5V	1	1.6	—	mA
V_{IH}	"H" Input Voltage	5V	—	3.5	—	5	V
V_{IL}	"L" Input Voltage	5V	—	0	—	1	V
f_{OSC}	Oscillator Frequency	5V	R_{OSC}=51kΩ	—	150	—	kHz

Functional Description

Operation

The 2^{12} series of decoders provides various combinations of addresses and data pins in different packages so as to pair with the 2^{12} series of encoders.

The decoders receive data that are transmitted by an encoder and interpret the first N bits of code period as addresses and the last 12–N bits as data, where N is the address code number. A signal on the DIN pin activates the oscillator which in turn decodes the incoming address and data. The decoders will then check the received address three times continuously. If the received address codes all match the contents of the decoder's local address, the 12–N bits of data are decoded to activate the output pins and the VT pin is set high to indicate a valid transmission. This will last unless the address code is incorrect or no signal is received.

The output of the VT pin is high only when the transmission is valid. Otherwise it is always low.

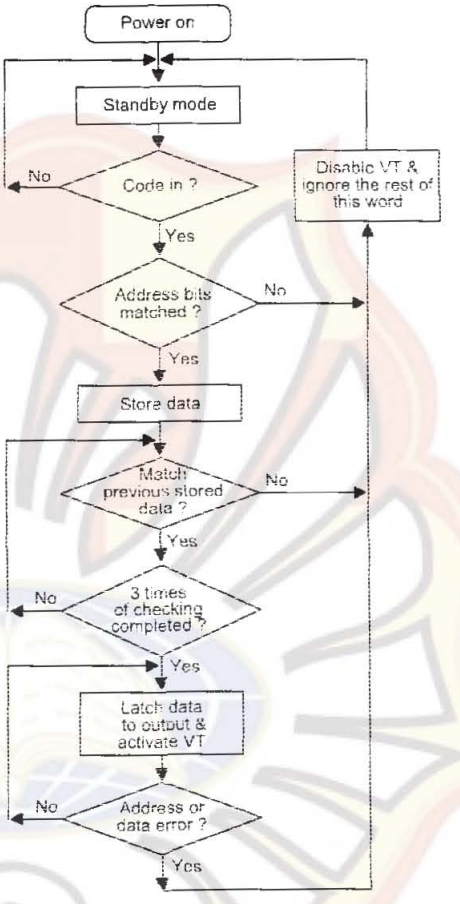
Output type

Of the 2^{12} series of decoders, the HT12F has no data output pin but its VT pin can be used as a momentary data output. The HT12D, on the other hand, provides 4 latch type data pins whose data remain unchanged until new data are received.

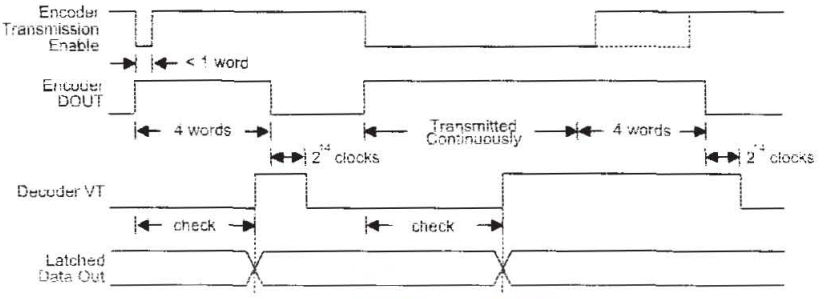
Part No.	Data Pins	Address Pins	Output Type	Operating Voltage
HT12D	4	8	Latch	2.4V~12V
HT12F	0	12	—	2.4V~12V

Flowchart

The oscillator is disabled in the standby state and activated when a logic "high" signal applies to the DIN pin. That is to say, the DIN should be kept low if there is no signal input.



Decoder timing



Encoder/Decoder cross reference table

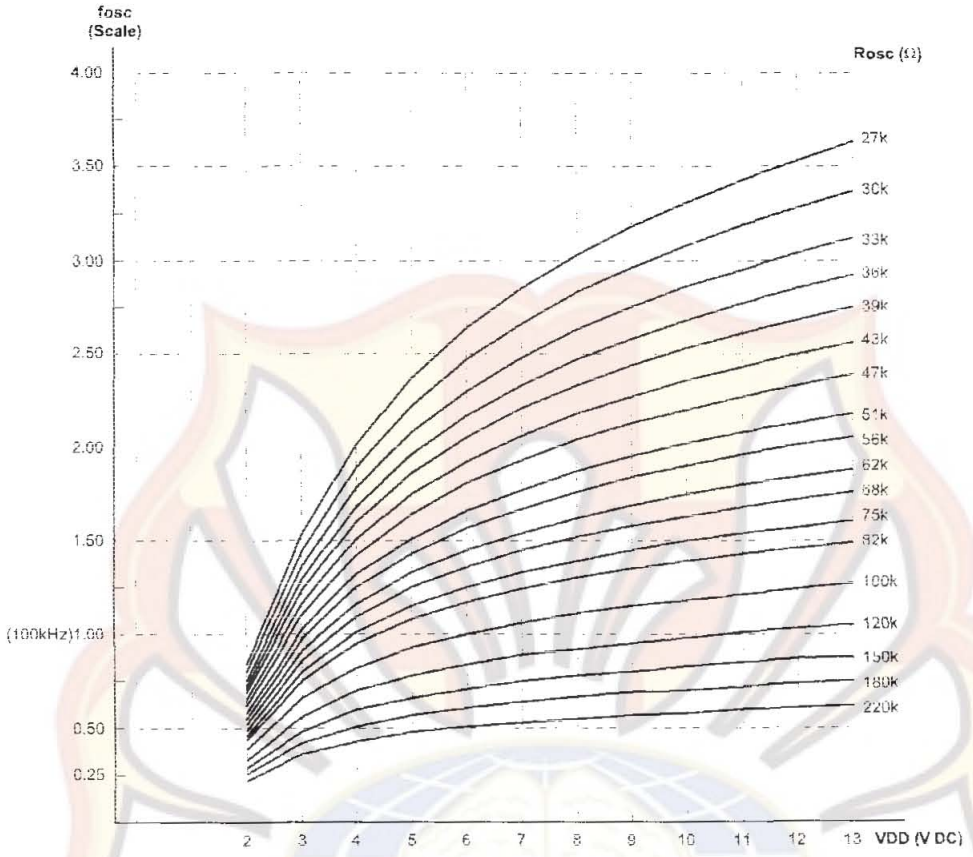
Decoders Part No.	Data Pins	Address Pins	VT	Pair Encoder	Package			
					Encoder		Decoder	
					DIP	SOP	DIP	SOP
HT12D	4	8	√	HT12A	18	20	18	20
				HT12E	18	20		
HT12F	0	12	√	HT12A	18	20	18	20
				HT12E	18	20		

Address/Data sequence

The following table provides address/data sequence for various models of the 2^{12} series of decoders. A correct device should be chosen according to the requirements of the individual addresses and data.

Part No.	Address/Data Bits											
	0	1	2	3	4	5	6	7	8	9	10	11
HT12D	A0	A1	A2	A3	A4	A5	A6	A7	D8	D9	D10	D11
HT12F	A0	A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11

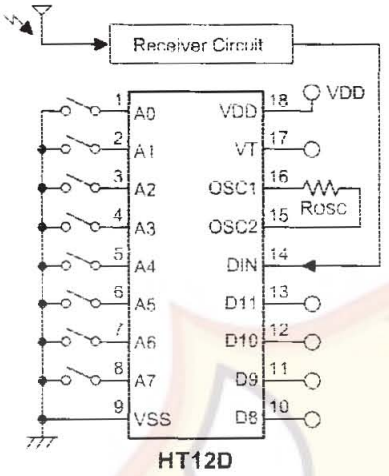
Oscillator frequency vs supply voltage

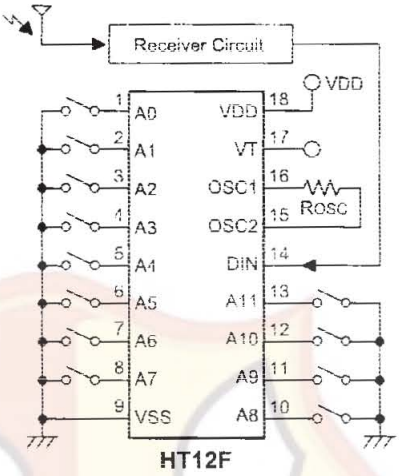


The recommended oscillator frequency is f_{OSCD} (decoder) $\cong 50\ f_{OSCE}$ (HT12E encoder)

$$\cong \frac{1}{3} f_{OSCE} \text{ (HT12A encoder).}$$

Application Circuits





Notes: Typical infrared receiver: PIC-12043T/PIC-12043S (KODESIII CORP.)
or LTM9052 (LITEON CORP.)

Typical RF receiver: JR-200 (JUWA CORP.)
RE-99 (MING MICROSYSTEM, U.S.A.)

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atures

- ompatible with MCS®-51 Products
- Bytes of In-System Programmable (ISP) Flash Memory
  - Endurance: 1000 Write/Erase Cycles
- 0V to 5.5V Operating Range
- lly Static Operation: 0 Hz to 33 MHz
- ree-level Program Memory Lock
- 8 x 8-bit Internal RAM
- Programmable I/O Lines
- wo 16-bit Timer/Counters
- x Interrupt Sources
- ll Duplex UART Serial Channel
- w-power Idle and Power-down Modes
- errupt Recovery from Power-down Mode
- atchdog Timer
- ual Data Pointer
- wer-off Flag
- st Programming Time
- exible ISP Programming (Byte and Page Mode)

scription

AT89S51 is a low-power, high-performance CMOS 8-bit microcontroller with 4K s of In-System Programmable Flash memory. The device is manufactured using el's high-density nonvolatile memory technology and is compatible with the indus- standard 80C51 instruction set and pinout. The on-chip Flash allows the program nory to be reprogrammed in-system or by a conventional nonvolatile memory pro- mmer. By combining a versatile 8-bit CPU with In-System Programmable Flash on onolithic chip, the Atmel AT89S51 is a powerful microcontroller which provides a ly-flexible and cost-effective solution to many embedded control applications.

AT89S51 provides the following standard features: 4K bytes of Flash, 128 bytes of M, 32 I/O lines, Watchdog timer, two data pointers, two 16-bit timer/counters, a five- or two-level interrupt architecture, a full duplex serial port, on-chip oscillator, and k circuitry. In addition, the AT89S51 is designed with static logic for operation n to zero frequency and supports two software selectable power saving modes. Idle Mode stops the CPU while allowing the RAM, timer/counters, serial port, and rrupt system to continue functioning. The Power-down mode saves the RAM con- s but freezes the oscillator, disabling all other chip functions until the next external rrupt or hardware reset.

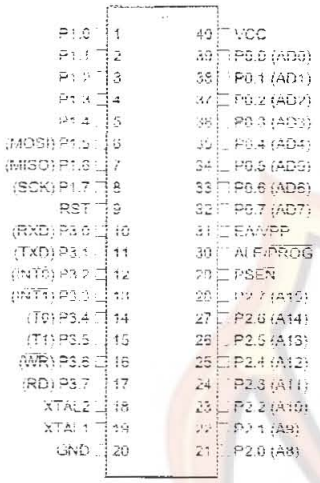
8-bit Microcontroller with 4K Bytes In-System Programmable Flash

AT89S51

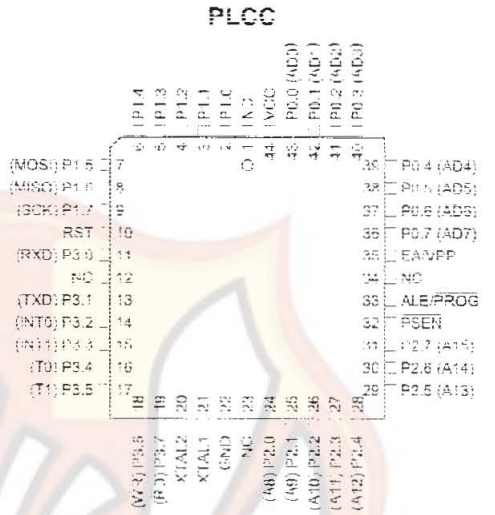
2487B–MICRO–12/03

Configurations

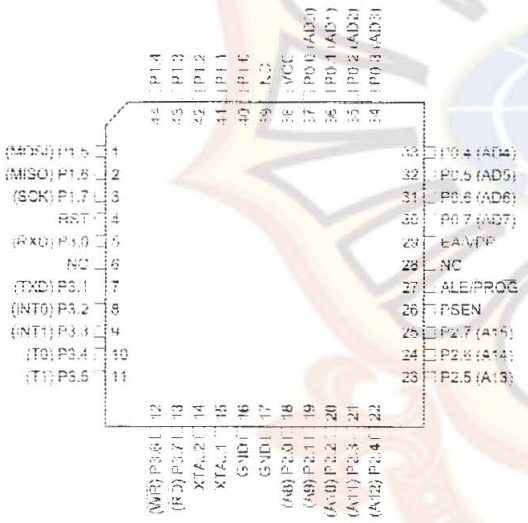
PDIP



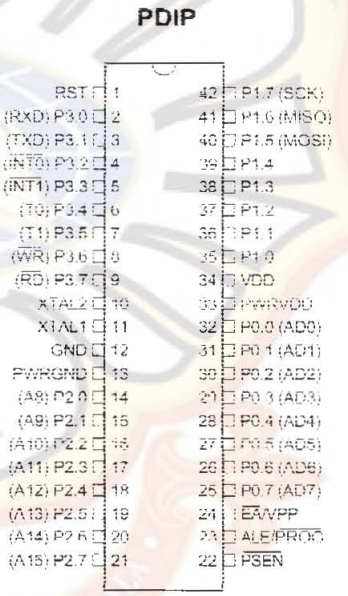
PLCC



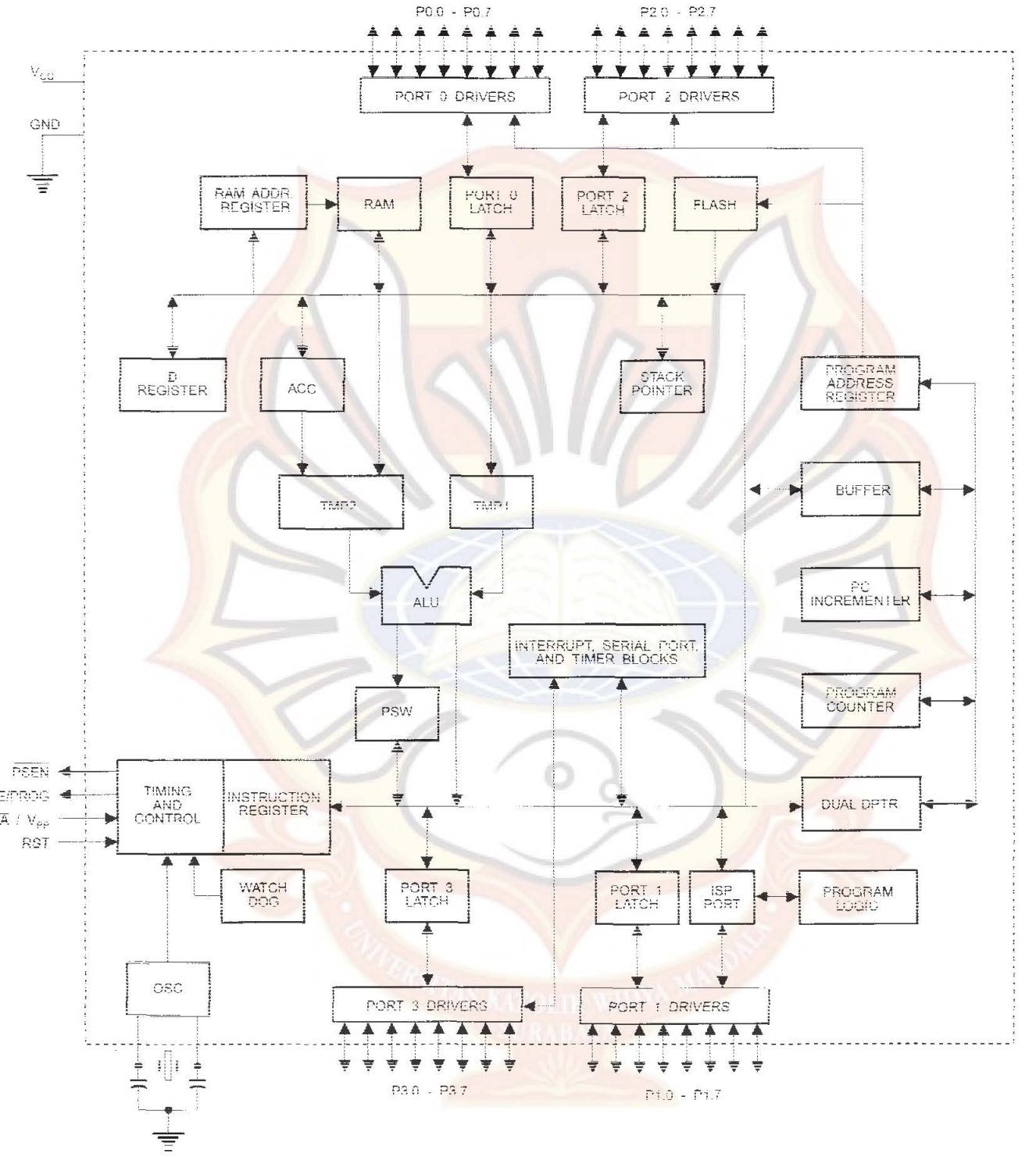
TQFP



PDIP



ock Diagram


P0.0 - P0.7
P2.0 - P2.7
PORT 0 DRIVERS
PORT 2 DRIVERS
RAM ADDR REGISTER
RAM
PORT 0 LATCH
PORT 2 LATCH
FLASH
B REGISTER
ACC
STACK POINTER
PROGRAM ADDRESS REGISTER
BUFFER
TMP2
TMP1
ALU
PC INCREMENTER
INTERRUPT, SERIAL PORT, AND TIMER BLOCKS
PSW
PROGRAM COUNTER
TIMING AND CONTROL
INSTRUCTION REGISTER
DUAL DPTR
WATCH DOG
PORT 3 LATCH
PORT 1 LATCH
ISP PORT
PROGRAM LOGIC
OSC
PORT 3 DRIVERS
PORT 1 DRIVERS
P3.0 - P3.7
P1.0 - P1.7
GND
RST

Description

C

Supply voltage (all packages except 42-PDIP).

D

Ground (all packages except 42-PDIP; for 42-PDIP GND connects only the logic core and the embedded program memory).

D

Supply voltage for the 42-PDIP which connects only the logic core and the embedded program memory.

RVDD

Supply voltage for the 42-PDIP which connects only the I/O Pad Drivers. The application board **MUST** connect both VDD and PWRVDD to the board supply voltage.

RGND

Ground for the 42-PDIP which connects only the I/O Pad Drivers. PWRGND and GND are weakly connected through the common silicon substrate, but not through any metal link. The application board **MUST** connect both GND and PWRGND to the board ground.

t 0

Port 0 is an 8-bit open drain bi-directional I/O port. As an output port, each pin can sink eight TTL inputs. When 1s are written to port 0 pins, the pins can be used as high-impedance inputs.

Port 0 can also be configured to be the multiplexed low-order address/data bus during accesses to external program and data memory. In this mode, P0 has internal pull-ups.

Port 0 also receives the code bytes during Flash programming and outputs the code bytes during program verification. **External pull-ups are required during program verification.**

t 1

Port 1 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 1 output buffers can sink/source four TTL inputs. When 1s are written to Port 1 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current (I_{IL}) because of the internal pull-ups.

Port 1 also receives the low-order address bytes during Flash programming and verification.

Port Pin	Alternate Functions
P1.5	MOSI (used for In-System Programming)
P1.6	MISO (used for In-System Programming)
P1.7	SCK (used for In-System Programming)

t 2

Port 2 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 2 output buffers can sink/source four TTL inputs. When 1s are written to Port 2 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally being pulled low will source current (I_{IL}) because of the internal pull-ups.

Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @ DPTR). In this application, Port 2 uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ RI), Port 2 emits the contents of the P2 Special Function Register.

Port 2 also receives the high-order address bits and some control signals during Flash programming and verification.

t 3

Port 3 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}) because of the pull-ups.

Port 3 receives some control signals for Flash programming and verification.

Port 3 also serves the functions of various special features of the AT89S51, as shown in the following table.

Port Pin	Alternate Functions
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	$\overline{INT0}$ (external interrupt 0)
P3.3	$\overline{INT1}$ (external interrupt 1)
P3.4	T0 (timer 0 external input)
P3.5	T1 (timer 1 external input)
P3.6	$\overline{WR}$ (external data memory write strobe)
P3.7	$\overline{RD}$ (external data memory read strobe)

T

Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device. This pin drives High for 98 oscillator periods after the Watchdog times out. The DISRTO bit in SFR AUXR (address 8EH) can be used to disable this feature. In the default state of bit DISRTO, the RESET HIGH out feature is enabled.

E/$\overline{PROG}$

Address Latch Enable (ALE) is an output pulse for latching the low byte of the address during accesses to external memory. This pin is also the program pulse input ($\overline{PROG}$) during Flash programming.

In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external data memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX or MOVC instruction. Otherwise, the pin is weakly pulled high. Setting the ALE-disable bit has no effect if the microcontroller is in external execution mode.

$\overline{EN}$

Program Store Enable ($\overline{PSEN}$) is the read strobe to external program memory.

When the AT89S51 is executing code from external program memory, $\overline{PSEN}$ is activated twice each machine cycle, except that two $\overline{PSEN}$ activations are skipped during each access to external data memory.

/VPP

External Access Enable. $\overline{EA}$ must be strapped to GND in order to enable the device to fetch code from external program memory locations starting at 0000H up to FFFFH. Note, however, that if lock bit 1 is programmed, $\overline{EA}$ will be internally latched on reset.

$\overline{EA}$ should be strapped to V_{CC} for internal program executions.

This pin also receives the 12-volt programming enable voltage (V_{PP}) during Flash programming.

AL1

Input to the inverting oscillator amplifier and input to the internal clock operating circuit.

AL2

Output from the inverting oscillator amplifier

ecial nction gisters

A map of the on-chip memory area called the Special Function Register (SFR) space is shown in Table 1.

Note that not all of the addresses are occupied, and unoccupied addresses may not be implemented on the chip. Read accesses to these addresses will in general return random data, and write accesses will have an indeterminate effect.

e 1. AT89S51 SFR Map and Reset Values

F8H									0FFH
F0H	B 00000000								0F7H
E8H									0EFH
E0H	ACC 00000000								0E7H
D8H									0DFH
D0H	PSW 00000000								0D7H
C8H									0CFH
C0H									0C7H
B8H	IP XX000000								0BFH
B0H	P3 11111111								0B7H
A8H	IE 0X000000								0AFH
A0H	P2 11111111		AUXR1 XXXXXXX0				WDTRST XXXXXXXX		0A7H
98H	SCON 00000000	SBUF XXXXXXXX							9FH
90H	P1 11111111								97H
88H	TCON 00000000	TMOD 00000000	TL0 00000000	TL1 00000000	TH0 00000000	TH1 00000000	AUXR XXX00XX0		8FH
80H	P0 11111111	SP 00000111	DP0L 00000000	DP0H 00000000	DP1L 00000000	DP1H 00000000		PCON 0XXX0000	87H

User software should not write 1s to these unlisted locations, since they may be used in future products to invoke new features. In that case, the reset or inactive values of the new bits will always be 0.

Interrupt Registers: The individual interrupt enable bits are in the IE register. Two priorities can be set for each of the five interrupt sources in the IP register.

Table 2. AUXR: Auxiliary Register

AUXR Address = 8EH Reset Value = XXX00XX0B

Not Bit Addressable

	–	–	–	WDIDLE	DISRTO	–	–	DISALE
Bit	7	6	5	4	3	2	1	0

– Reserved for future expansion

DISALE Disable/Enable ALE

DISALE Operating Mode

0 ALE is emitted at a constant rate of 1/6 the oscillator frequency

1 ALE is active only during a MOVX or MOVC instruction

DISRTO Disable/Enable Reset-out

DISRTO

0 Reset pin is driven High after WDT times out

1 Reset pin is input only

WDIDLE Disable/Enable WDT in IDLE mode

WDIDLE

0 WDT continues to count in IDLE mode

1 WDT halts counting in IDLE mode

Dual Data Pointer Registers: To facilitate accessing both internal and external data memory, two banks of 16-bit Data Pointer Registers are provided: DP0 at SFR address locations 82H-83H and DP1 at 84H-85H. Bit DPS = 0 in SFR AUXR1 selects DP0 and DPS = 1 selects DP1. The user should **ALWAYS** initialize the DPS bit to the appropriate value before accessing the respective Data Pointer Register.

Power Off Flag: The Power Off Flag (POF) is located at bit 4 (PCON.4) in the PCON SFR. POF is set to "1" during power up. It can be set and rest under software control and is not affected by reset.

Table 3. AUXR1: Auxiliary Register 1

AUXR1 Address A2H Reset Value - XXXXXXX0B

Not Bit Addressable

	–	–	–	–	–	–	DPS
Bit	7	6	5	4	3	2	1	0

– Reserved for future expansion

DPS Data Pointer Register Select

DPS	
0	Selects DPTR Registers DP0L, DP0H
1	Selects DPTR Registers DP1L, DP1H

mory ganization

MCS-51 devices have a separate address space for Program and Data Memory. Up to 64K bytes each of external Program and Data Memory can be addressed.

gram Memory

If the $\overline{EA}$ pin is connected to GND, all program fetches are directed to external memory.

On the AT89S51, if $\overline{EA}$ is connected to V_{CC}, program fetches to addresses 0000H through FFFH are directed to internal memory and fetches to addresses 1000H through FFFFH are directed to external memory.

a Memory

The AT89S51 implements 128 bytes of on-chip RAM. The 128 bytes are accessible via direct and indirect addressing modes. Stack operations are examples of indirect addressing, so the 128 bytes of data RAM are available as stack space.

tchdog ner ne-time abled with set-out)

The WDT is intended as a recovery method in situations where the CPU may be subjected to software upsets. The WDT consists of a 14-bit counter and the Watchdog Timer Reset (WDTRST) SFR. The WDT is defaulted to disable from exiting reset. To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, it will increment every machine cycle while the oscillator is running. The WDT timeout period is dependent on the external clock frequency. There is no way to disable the WDT except through reset (either hardware reset or WDT overflow reset). When WDT overflows, it will drive an output RESET HIGH pulse at the RST pin.

ing the WDT

To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, the user needs to service it by writing 01EH and 0E1H to WDTRST to avoid a WDT overflow. The 14-bit counter overflows when it reaches 16383 (3FFFH), and this will reset the device. When the WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must reset the WDT at least every 16383 machine cycles. To reset the WDT the user must write 01EH and 0E1H to WDTRST. WDTRST is a write-only register. The WDT counter cannot be read or written. When WDT overflows, it will generate an output RESET pulse at the RST pin. The RESET pulse duration is 98xTOSC, where TOSC = 1/FOSC. To make the best use of the WDT, it should be serviced in those sections of code that will periodically be executed within the time required to prevent a WDT reset.

DT During wer-down d Idle

In Power-down mode the oscillator stops, which means the WDT also stops. While in Power-down mode, the user does not need to service the WDT. There are two methods of exiting Power-down mode: by a hardware reset or via a level-activated external interrupt, which is enabled prior to entering Power-down mode. When Power-down is exited with hardware reset, servicing the WDT should occur as it normally does whenever the AT89S51 is reset. Exiting Power-down with an interrupt is significantly different. The interrupt is held low long enough for the oscillator to stabilize. When the interrupt is brought high, the interrupt is serviced. To prevent the WDT from resetting the device while the interrupt pin is held low, the WDT is not started until the interrupt is pulled high. It is suggested that the WDT be reset during the interrupt service for the interrupt used to exit Power-down mode.

To ensure that the WDT does not overflow within a few states of exiting Power-down, it is best to reset the WDT just before entering Power-down mode.

Before going into the IDLE mode, the WDIDLE bit in SFR AUXR is used to determine whether the WDT continues to count if enabled. The WDT keeps counting during IDLE (WDIDLE bit = 0) as the default state. To prevent the WDT from resetting the AT89S51 while in IDLE mode, the user should always set up a timer that will periodically exit IDLE, service the WDT, and reenter IDLE mode.

With WDIDLE bit enabled, the WDT will stop to count in IDLE mode and resumes the count upon exit from IDLE.

RT

The UART in the AT89S51 operates the same way as the UART in the AT89C51. For further information on the UART operation, refer to the Atmel Web site (http://www.atmel.com). From the home page, select "Products", then "Microcontrollers", then "8051-Architecture", then "Documentation", and "Other Documents". Open the Adobe® Acrobat® file "AT89 Series Hardware Description".

ner 0 and 1

Timer 0 and Timer 1 in the AT89S51 operate the same way as Timer 0 and Timer 1 in the AT89C51. For further information on the timers' operation, refer to the Atmel Web site (http://www.atmel.com). From the home page, select "Products", then "Microcontrollers", then "8051-Architecture", then "Documentation", and "Other Documents". Open the Adobe Acrobat file "AT89 Series Hardware Description".

errupts

The AT89S51 has a total of five interrupt vectors: two external interrupts ($\overline{INT0}$ and $\overline{INT1}$), two timer interrupts (Timers 0 and 1), and the serial port interrupt. These interrupts are all shown in Figure 1.

Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in Special Function Register IE. IE also contains a global disable bit, EA, which disables all interrupts at once.

Note that Table 4 shows that bit positions IE.6 and IE.5 are unimplemented. User software should not write 1s to these bit positions, since they may be used in future AT89 products.

The Timer 0 and Timer 1 flags, TF0 and TF1, are set at S5P2 of the cycle in which the timers overflow. The values are then polled by the circuitry in the next cycle.

Table 4. Interrupt Enable (IE) Register

(MSB)							(LSB)
EA	–	–	ES	ET1	EX1	ET0	EX0

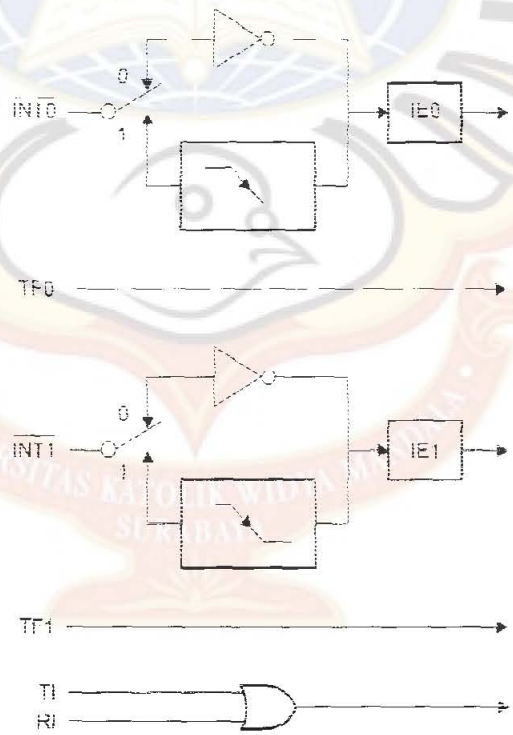
Enable Bit = 1 enables the interrupt.

Enable Bit = 0 disables the interrupt.

Symbol	Position	Function
EA	IE.7	Disables all interrupts. If EA = 0, no interrupt is acknowledged. If EA = 1, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.
–	IE.6	Reserved
–	IE.5	Reserved
ES	IE.4	Serial Port interrupt enable bit
ET1	IE.3	Timer 1 interrupt enable bit
EX1	IE.2	External interrupt 1 enable bit
ET0	IE.1	Timer 0 interrupt enable bit
EX0	IE.0	External interrupt 0 enable bit

User software should never write 1s to reserved bits, because they may be used in future AT89 products.

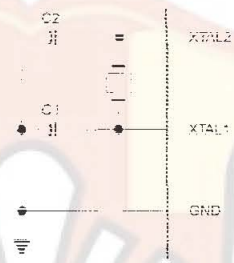
Figure 1. Interrupt Sources



cillator aracteristics

XTAL 1 and XTAL 2 are the input and output, respectively, of an inverting amplifier that can be configured for use as an on-chip oscillator, as shown in Figure 2. Either a quartz crystal or ceramic resonator may be used. To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven, as shown in Figure 3. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum voltage high and low time specifications must be observed.

Figure 2. Oscillator Connections



Note: C1, C2 = 30 pF ± 10 pF for Crystals
= 40 pF ± 10 pF for Ceramic Resonators

Figure 3. External Clock Drive Configuration

e Mode

In idle mode, the CPU puts itself to sleep while all the on-chip peripherals remain active. The mode is invoked by software. The content of the on-chip RAM and all the special function registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

Note that when idle mode is terminated by a hardware reset, the device normally resumes program execution from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when idle mode is terminated by a reset, the instruction following the one that invokes idle mode should not write to a port pin or to external memory.

wer-down ode

In the Power-down mode, the oscillator is stopped, and the instruction that invokes Power-down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the Power-down mode is terminated. Exit from Power-down mode can be initiated either by a hardware reset or by activation of an enabled external interrupt (INT0 or INT1). Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before V_{CC} is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

Table 5. Status of External Pins During Idle and Power-down Modes

Mode	Program Memory	ALE	$\overline{PSEN}$	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

ogram mory Lock s

The AT89S51 has three lock bits that can be left unprogrammed (U) or can be programmed (P) to obtain the additional features listed in the following table.

Table 6. Lock Bit Protection Modes

Program Lock Bits				
	LB1	LB2	LB3	Protection Type
1	U	U	U	No program lock features
2	P	U	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset, and further programming of the Flash memory is disabled
3	P	P	U	Same as mode 2, but verify is also disabled
4	P	P	P	Same as mode 3, but external execution is also disabled

When lock bit 1 is programmed, the logic level at the $\overline{EA}$ pin is sampled and latched during reset. If the device is powered up without a reset, the latch initializes to a random value and holds that value until reset is activated. The latched value of EA must agree with the current logic level at that pin in order for the device to function properly.

ogramming Flash – rallel Mode

The AT89S51 is shipped with the on-chip Flash memory array ready to be programmed. The programming interface needs a high-voltage (12-volt) program enable signal and is compatible with conventional third-party Flash or EPROM programmers.

The AT89S51 code memory array is programmed byte-by-byte.

Programming Algorithm: Before programming the AT89S51, the address, data, and control signals should be set up according to the Flash Programming Modes table (Table 7) and Figures 4 and 5. To program the AT89S51, take the following steps:

1. Input the desired memory location on the address lines.
2. Input the appropriate data byte on the data lines.
3. Activate the correct combination of control signals.
4. Raise $\overline{EA}/V_{pp}$ to 12V.
5. Pulse ALE/$\overline{PROG}$ once to program a byte in the Flash array or the lock bits. The byte-write cycle is self-timed and typically takes no more than 50 µs. Repeat steps 1 through 5, changing the address and data for the entire array or until the end of the object file is reached.

$\overline{Data}$ Polling: The AT89S51 features $\overline{Data}$ Polling to indicate the end of a byte write cycle. During a write cycle, an attempted read of the last byte written will result in the complement of the written data on P0.7. Once the write cycle has been completed, true data is valid on all outputs, and the next cycle may begin. $\overline{Data}$ Polling may begin any time after a write cycle has been initiated.

Ready/$\overline{\text{Busy}}$: The progress of byte programming can also be monitored by the RDY/$\overline{\text{BSY}}$ output signal. P3.0 is pulled low after ALE goes high during programming to indicate $\overline{\text{BUSY}}$. P3.0 is pulled high again when programming is done to indicate READY.

Program Verify: If lock bits LB1 and LB2 have not been programmed, the programmed code data can be read back via the address and data lines for verification. **The status of the individual lock bits can be verified directly by reading them back.**

Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 000H, 100H, and 200H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows.

(000H) = 1EH indicates manufactured by Atmel
(100H) = 51H indicates AT89S51
(200H) = 06H

Chip Erase: In the parallel programming mode, a chip erase operation is initiated by using the proper combination of control signals and by pulsing ALE/$\overline{\text{PROG}}$ low for a duration of 200 ns - 500 ns.

In the serial programming mode, a chip erase operation is initiated by issuing the Chip Erase instruction. In this mode, chip erase is self-timed and takes about 500 ms.

During chip erase, a serial read from any address location will return 00H at the data output.

ogramming
Flash –
rial Mode

The Code memory array can be programmed using the serial ISP interface while RST is pulled to V_{CC}. The serial interface consists of pins SCK, MOSI (input) and MISO (output). After RST is set high, the Programming Enable instruction needs to be executed first before other operations can be executed. Before a reprogramming sequence can occur, a Chip Erase operation is required.

The Chip Erase operation turns the content of every memory location in the Code array into FFH.

Either an external system clock can be supplied at pin XTAL1 or a crystal needs to be connected across pins XTAL1 and XTAL2. The maximum serial clock (SCK) frequency should be less than 1/16 of the crystal frequency. With a 33 MHz oscillator clock, the maximum SCK frequency is 2 MHz.

ial
gramming
orithm

To program and verify the AT89S51 in the serial programming mode, the following sequence is recommended:

1. Power-up sequence:
   Apply power between VCC and GND pins.
   Set RST pin to "H".
   If a crystal is not connected across pins XTAL1 and XTAL2, apply a 3 MHz to 33 MHz clock to XTAL1 pin and wait for at least 10 milliseconds.
2. Enable serial programming by sending the Programming Enable serial instruction to pin MOSI/P1.5. The frequency of the shift clock supplied at pin SCK/P1.7 needs to be less than the CPU clock at XTAL1 divided by 16.
3. The Code array is programmed one byte at a time in either the Byte or Page mode. The write cycle is self-timed and typically takes less than 0.5 ms at 5V.
4. Any memory location can be verified by using the Read instruction that returns the content at the selected address at serial output MISO/P1.6.
5. At the end of a programming session, RST can be set low to commence normal device operation.

Power-off sequence (if needed):

Set XTAL1 to "L" (if a crystal is not used).

Set RST to "L".

Turn V_{CC} power off.

Data Polling: The $\overline{\text{Data}}$ Polling feature is also available in the serial mode. In this mode, during a write cycle an attempted read of the last byte written will result in the complement of the MSB of the serial output byte on MISO.

ial ogramming ruction Set

The Instruction Set for Serial Programming follows a 4-byte protocol and is shown in Table 8.

ogramming erface – rallel Mode

Every code byte in the Flash array can be programmed by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

Most major worldwide programming vendors offer worldwide support for the Atmel AT89 microcontroller series. Please contact your local programming vendor for the appropriate software revision.

e 7. Flash Programming Modes

de	V_{CC}	RST	$\overline{\text{PSEN}}$	ALE/$\overline{\text{PROG}}$	$\overline{\text{EA}}$/V_{PP}	P2.6	P2.7	P3.3	P3.6	P3.7	P0.7-0 Data	P2.3-0 Address	P1.7-0 Address
e Code Data	5V	H	L	(2)	12V	L	H	H	H	H	D_{IN}	A11-8	A7-0
ad Code Data	5V	H	L	H	H	L	L	L	H	H	D_{OUT}	A11-8	A7-0
e Lock Bit 1	5V	H	L	(3)	12V	H	H	H	H	H	X	X	X
e Lock Bit 2	5V	H	L	(3)	12V	H	H	H	L	L	X	X	X
e Lock Bit 3	5V	H	L	(3)	12V	H	L	H	H	L	X	X	X
ad Lock Bits 3	5V	H	L	H	H	H	H	L	H	L	P0.2, P0.3, P0.4	X	X
p Erase	5V	H	L	(1)	12V	H	L	H	L	L	X	X	X
ad Atmel ID	5V	H	L	H	H	L	L	L	L	L	1EH	0000	00H
ad Device ID	5V	H	L	H	H	L	L	L	L	L	01H	0001	00H
ad Device ID	5V	H	L	H	H	L	L	L	L	L	06H	0010	00H

s:
1. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Chip Erase.
2. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Write Code Data.
3. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Write Lock Bits.
4. RDY/$\overline{\text{BSY}}$ signal is output on P3.0 during programming.
5. X = don't care.

Figure 4. Programming the Flash Memory (Parallel Mode)

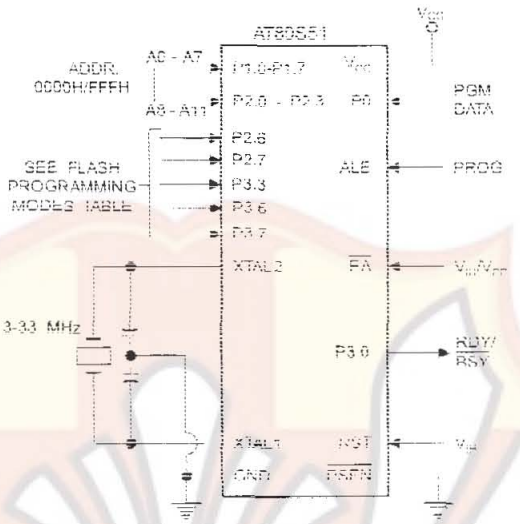
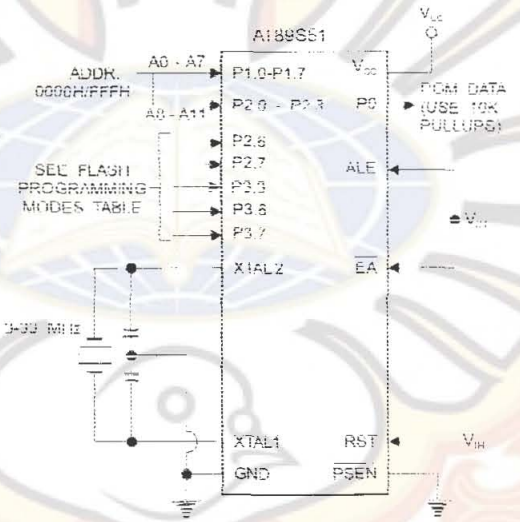


Figure 5. Verifying the Flash Memory (Parallel Mode)

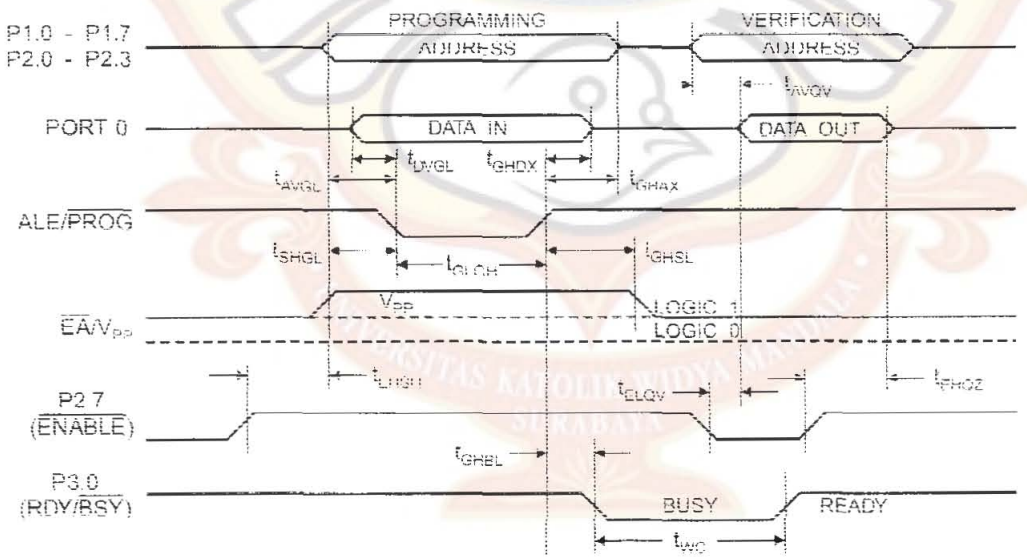


sh Programming and Verification Characteristics (Parallel Mode)

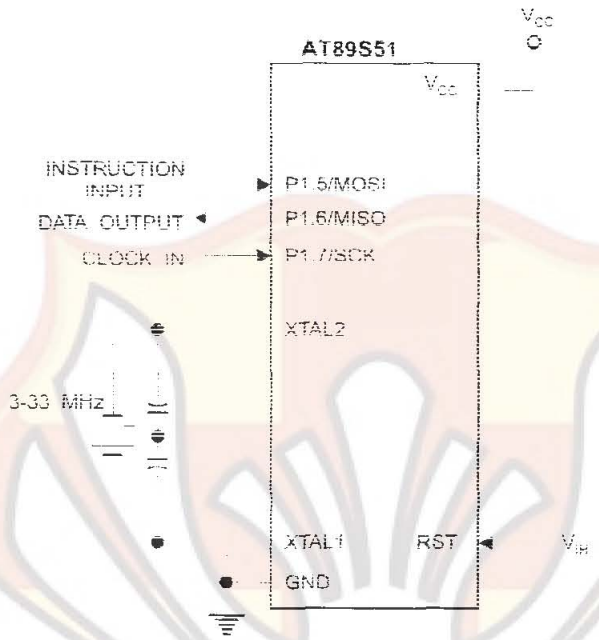
20°C to 30°C, V_{CC} = 4.5 to 5.5V

nbol	Parameter	Min	Max	Units
	Programming Supply Voltage	11.5	12.5	V
	Programming Supply Current		10	mA
	V_{CC} Supply Current		30	mA
LCL	Oscillator Frequency	3	33	MHz
AVGL	Address Setup to $\overline{PROG}$ Low	$48t_{CLCL}$		
GHAX	Address Hold After $\overline{PROG}$	$48t_{CLCL}$		
DVGL	Data Setup to $\overline{PROG}$ Low	$48t_{CLCL}$		
GHDX	Data Hold After $\overline{PROG}$	$48t_{CLCL}$		
EHSH	P2.7 ($\overline{ENABLE}$) High to V_{PP}	$48t_{CLCL}$		
SHGL	V_{PP} Setup to $\overline{PROG}$ Low	10		µs
GHSL	V_{PP} Hold After $\overline{PROG}$	10		µs
GLGH	$\overline{PROG}$ Width	0.2	1	µs
AVQV	Address to Data Valid		$48t_{CLCL}$	
ELQV	$\overline{ENABLE}$ Low to Data Valid		$48t_{CLCL}$	
EHQZ	Data Float After $\overline{ENABLE}$	0	$48t_{CLCL}$	
GLBL	$\overline{PROG}$ High to $\overline{BUSY}$ Low		1.0	µs
WC	Byte Write Cycle Time		50	µs

re 6. *Flash Programming and Verification Waveforms – Parallel Mode*

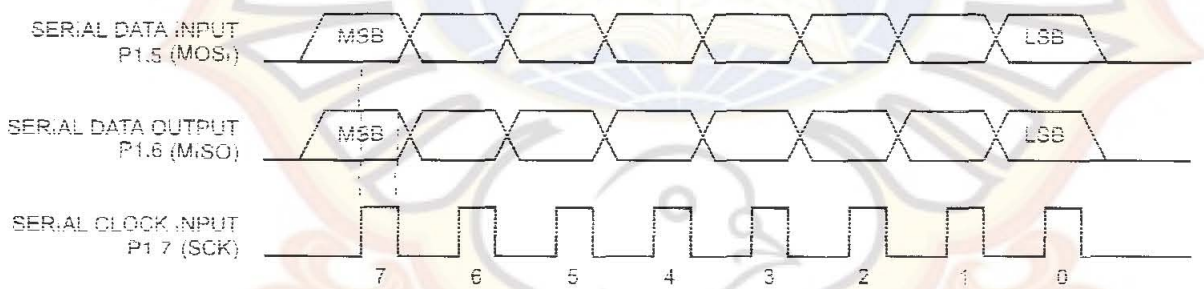


re 7. Flash Memory Serial Downloading



sh Programming and Verification Waveforms – Serial Mode

re 8. Serial Programming Waveforms



e 8. Serial Programming Instruction Set

	Instruction Format				
truction	Byte 1	Byte 2	Byte 3	Byte 4	Operation
gramming Enable	1010 1100	0101 0011	xxxx xxxx	xxxx xxxx 0110 1001 (Output on MISO)	Enable Serial Programming while RST is high
p Erase	1010 1100	100x xxxx	xxxx xxxx	xxxx xxxx	Chip Erase Flash memory array
ad Program Memory te Mode)	0010 0000	xxxx A11 A10 A9 A8	A7 A6 A5 A4 A3 A2 A1 A0	D7 D6 D5 D4 D3 D2 D1 D0	Read data from Program memory in the byte mode
te Program Memory te Mode)	0100 0000	xxxx A11 A10 A9 A8	A7 A6 A5 A4 A3 A2 A1 A0	D7 D6 D5 D4 D3 D2 D1 D0	Write data to Program memory in the byte mode
te Lock Bits[1]	1010 1100	1110 00 B2 B1	xxxx xxxx	xxxx xxxx	Write Lock bits. See Note (1).
ad Lock Bits	0010 0100	xxxx xxxx	xxxx xxxx	xxx LB3 LB2 LB1 xx	Read back current status of the lock bits (a programmed lock bit reads back as a "1")
ad Signature Bytes	0010 1000	xxxx A11 A10 A9 A8	A7 xxx xxx0	Signature Byte	Read Signature Byte
ad Program Memory ge Mode)	0011 0000	xxxx A11 A10 A9 A8	Byte 0	Byte 1... Byte 255	Read data from Program memory in the Page Mode (256 bytes)
te Program Memory ge Mode)	0101 0000	xxxx A11 A10 A9 A8	Byte 0	Byte 1... Byte 255	Write data to Program memory in the Page Mode (256 bytes)

: 1. B1 = 0, B2 = 0 → Mode 1, no lock protection
B1 = 0, B2 = 1 → Mode 2, lock bit 1 activated
B1 = 1, B2 = 0 → Mode 3, lock bit 2 activated
B1 = 1, B2 = 1 → Mode 4, lock bit 3 activated

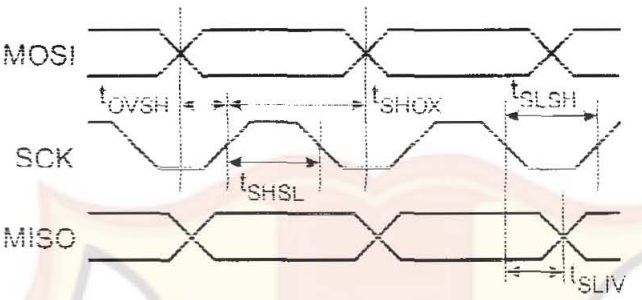
} Each of the lock bit modes need to be activated sequentially before Mode 4 can be executed.

After Reset signal is high, SCK should be low for at least 64 system clocks before it goes high to clock in the enable data bytes. No pulsing of Reset signal is necessary. SCK should be no faster than 1/16 of the system clock at XTAL1.

For Page Read/Write, the data always starts from byte 0 to 255. After the command byte and upper address byte are latched, each byte thereafter is treated as data until all 256 bytes are shifted in/out. Then the next instruction will be ready to be decoded.

erial Programming Characteristics

gure 9. Serial Programming Timing



ble 9. Serial Programming Characteristics, T_A = -40° C to 85° C, V_{CC} = 4.0 - 5.5V (Unless Otherwise Noted)

Symbol	Parameter	Min	Typ	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	3		33	MHz
CLCL	Oscillator Period	30			ns
SHSL	SCK Pulse Width High	8 t_{CLCL}			ns
SLSH	SCK Pulse Width Low	8 t_{CLCL}			ns
OVSH	MOSI Setup to SCK High	t_{CLCL}			ns
SHOX	MOSI Hold after SCK High	2 t_{CLCL}			ns
SLIV	SCK Low to MISO Valid	10	16	32	ns
ERASE	Chip Erase Instruction Cycle Time			500	ms
SWC	Serial Byte Write Cycle Time			64 t_{CLCL} + 400	µs

solute Maximum Ratings*

erating Temperature	-55°C to +125°C
rage Temperature	-65°C to +150°C
age on Any Pin Respect to Ground	-1.0V to +7.0V
imum Operating Voltage	6.6V
Output Current	15.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Characteristics

values shown in this table are valid for T_A = -40°C to 85°C and V_{CC} = 4.0V to 5.5V, unless otherwise noted.

nbol	Parameter	Condition	Min	Max	Units
	Input Low Voltage	(Except $\overline{EA}$)	0.5	0.2 V_{CC} 0.1	V
	Input Low Voltage ($\overline{EA}$)		-0.5	0.2 V_{CC}-0.3	V
	Input High Voltage	(Except XTAL1, RST)	0.2 V_{CC}+0.9	V_{CC}+0.5	V
	Input High Voltage	(XTAL1, RST)	0.7 V_{CC}	V_{CC}+0.5	V
	Output Low Voltage[1] (Ports 1,2,3)	I_{OL} = 1.6 mA		0.45	V
n	Output Low Voltage[1] (Port 0, ALE, $\overline{PSEN}$)	I_{OL} = 3.2 mA		0.45	V
	Output High Voltage (Ports 1,2,3, ALE, $\overline{PSEN}$)	I_{OH} = -60 µA, V_{CC} = 5V ± 10%	2.4		V
		I_{OH} = -25 µA	0.75 V_{CC}		V
		I_{OH} = -10 µA	0.9 V_{CC}		V
	Output High Voltage (Port 0 in External Bus Mode)	I_{OH} = -800 µA, V_{CC} = 5V ± 10%	2.4		V
1		I_{OH} = -300 µA	0.75 V_{CC}		V
		I_{OH} = -80 µA	0.9 V_{CC}		V
	Logical 0 Input Current (Ports 1,2,3)	V_{IN} = 0.45V		-50	µA
	Logical 1 to 0 Transition Current (Ports 1,2,3)	V_{IN} = 2V, V_{CC} = 5V ± 10%		-650	µA
	Input Leakage Current (Port 0, $\overline{EA}$)	0.45 < V_{IN} < V_{CC}		±10	µA
S1	Reset Pulldown Resistor		50	300	KΩ
	Pin Capacitance	Test Freq. = 1 MHz, T_A = 25°C		10	pF
	Power Supply Current	Active Mode, 12 MHz		25	mA
		Idle Mode, 12 MHz		6.5	mA
	Power-down Mode[2]	V_{CC} = 5.5V		50	µA

s: 1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
Maximum I_{OL} per port pin: 10 mA
Maximum I_{OL} per 8-bit port:
Port 0: 26 mA Ports 1, 2, 3: 15 mA
Maximum total I_{OL} for all output pins: 71 mA
If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
2. Minimum V_{CC} for Power-down is 2V.

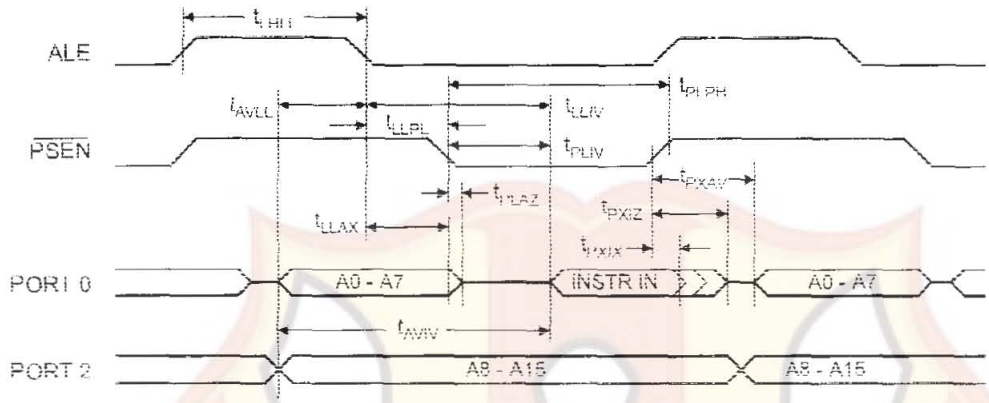
Characteristics

er operating conditions, load capacitance for Port 0, ALE/$\overline{PROG}$, and $\overline{PSEN}$ = 100 pF; load capacitance for all other uts = 80 pF.

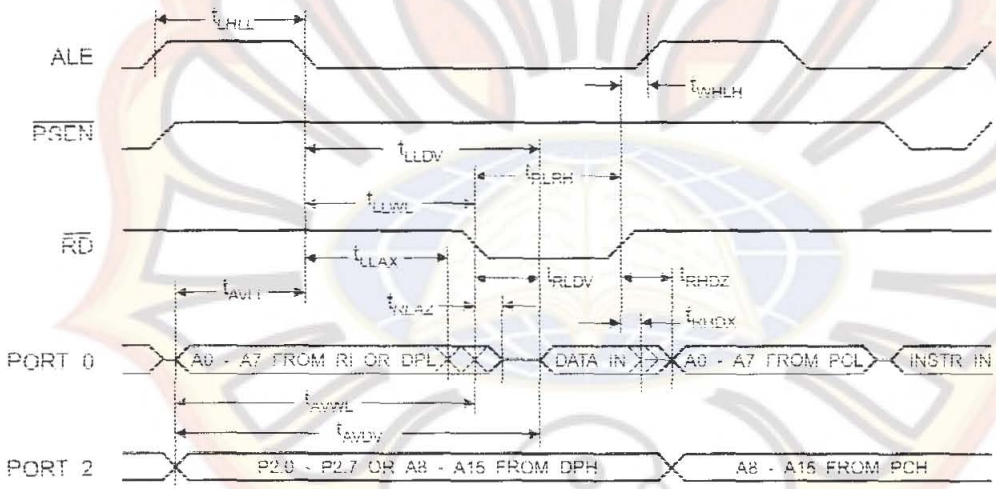
ternal Program and Data Memory Characteristics

mbol	Parameter	12 MHz Oscillator		Variable Oscillator		Units
		Min	Max	Min	Max	
LCL	Oscillator Frequency			0	33	MHz
L	ALE Pulse Width	127		$2t_{CLCL}$-40		ns
L	Address Valid to ALE Low	43		t_{CLCL}-25		ns
X	Address Hold After ALE Low	48		t_{CLCL}-25		ns
V	ALE Low to Valid Instruction In		233		$4t_{CLCL}$-65	ns
L	ALE Low to $\overline{PSEN}$ Low	43		t_{CLCL}-25		ns
H	$\overline{PSEN}$ Pulse Width	205		$3t_{CLCL}$-45		ns
V	$\overline{PSEN}$ Low to Valid Instruction In		145		$3t_{CLCL}$-60	ns
X	Input Instruction Hold After $\overline{PSEN}$	0		0		ns
Z	Input Instruction Float After $\overline{PSEN}$		59		t_{CLCL}-25	ns
V	$\overline{PSEN}$ to Address Valid	75		t_{CLCL}-8		ns
V	Address to Valid Instruction In		312		$5t_{CLCL}$-80	ns
LZ	$\overline{PSEN}$ Low to Address Float		10		10	ns
RH	$\overline{RD}$ Pulse Width	400		$6t_{CLCL}$-100		ns
WH	$\overline{WR}$ Pulse Width	400		$6t_{CLCL}$-100		ns
RV	$\overline{RD}$ Low to Valid Data In		252		$5t_{CLCL}$-90	ns
RDX	Data Hold After $\overline{RD}$	0		0		ns
RHZ	Data Float After $\overline{RD}$		97		$2t_{CLCL}$-28	ns
LDV	ALE Low to Valid Data In		517		$8t_{CLCL}$-150	ns
AVDV	Address to Valid Data In		585		$9t_{CLCL}$-165	ns
LWL	ALE Low to $\overline{RD}$ or $\overline{WR}$ Low	200	300	$3t_{CLCL}$-50	$3t_{CLCL}$+50	ns
AVWL	Address to $\overline{RD}$ or $\overline{WR}$ Low	203		$4t_{CLCL}$-75		ns
WHQX	Data Valid to $\overline{WR}$ Transition	23		t_{CLCL}-30		ns
QVWH	Data Valid to $\overline{WR}$ High	433		$7t_{CLCL}$-130		ns
WHDX	Data Hold After $\overline{WR}$	33		t_{CLCL}-25		ns
RLAZ	$\overline{RD}$ Low to Address Float		0		0	ns
WHLH	$\overline{RD}$ or $\overline{WR}$ High to ALE High	43	123	t_{CLCL}-25	t_{CLCL}+25	ns

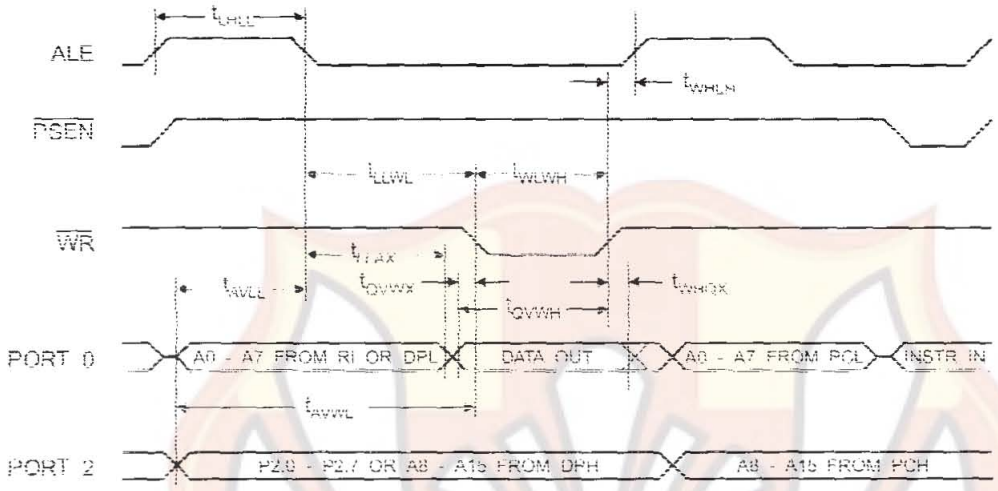
ternal Program Memory Read Cycle



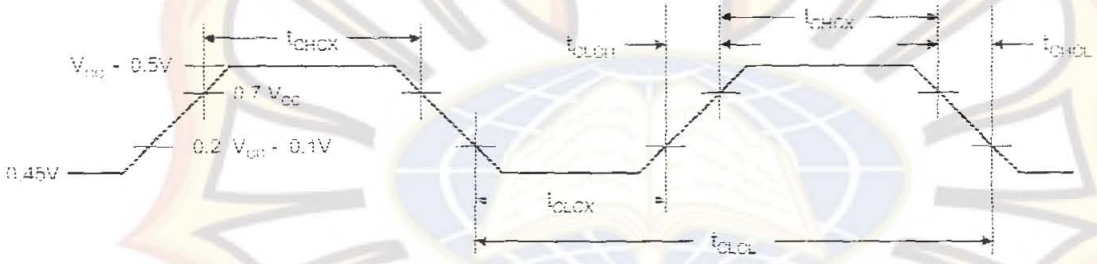
ternal Data Memory Read Cycle



ernal Data Memory Write Cycle



ternal Clock Drive Waveforms



ternal Clock Drive

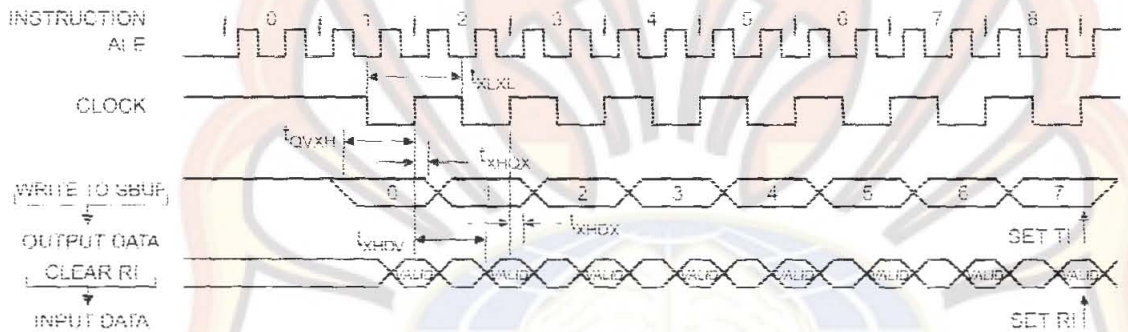
mbol	Parameter	Min	Max	Units
	Oscillator Frequency	0	33	MHz
	Clock Period	30		ns
	High Time	12		ns
	Low Time	12		ns
	Rise Time		5	ns
	Fall Time		5	ns

rial Port Timing: Shift Register Mode Test Conditions

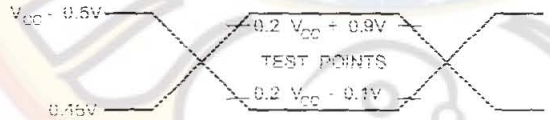
values in this table are valid for V_{CC} = 4.0V to 5.5V and Load Capacitance = 80 pF.

nbol	Parameter	12 MHz Osc		Variable Oscillator		Units
		Min	Max	Min	Max	
	Serial Port Clock Cycle Time	1.0		$12t_{CLCL}$		µs
	Output Data Setup to Clock Rising Edge	700		$10t_{CLCL}$-133		ns
	Output Data Hold After Clock Rising Edge	50		$2t_{CLCL}$-80		ns
	Input Data Hold After Clock Rising Edge	0		0		ns
	Clock Rising Edge to Input Data Valid		700		$10t_{CLCL}$-133	ns

ift Register Mode Timing Waveforms

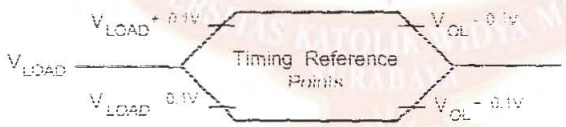


Testing Input/Output Waveforms[1]



1. AC Inputs during testing are driven at V_{CC} - 0.5V for a logic 1 and 0.45V for a logic 0. Timing measurements are made at V_{IH} min. for a logic 1 and V_{IL} max. for a logic 0.

eat Waveforms[1]



1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs.

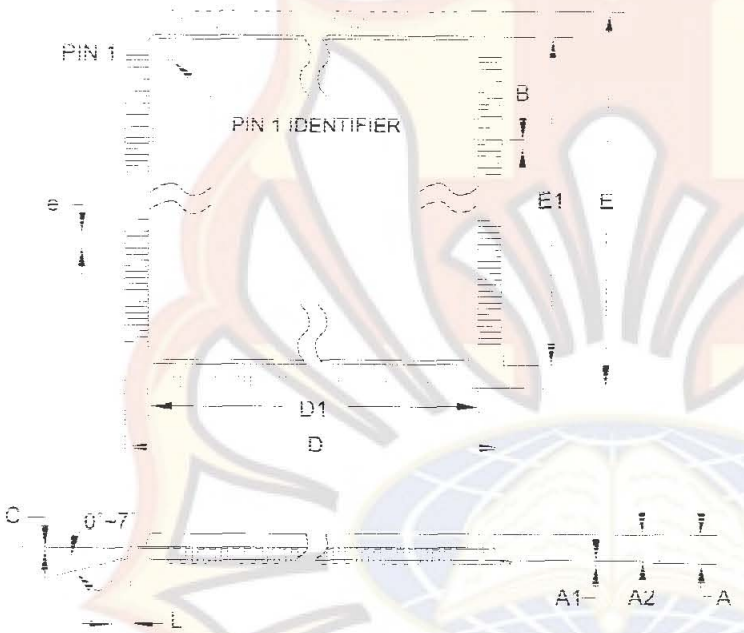
dering Information

peed MHz)	Power Supply	Ordering Code	Package	Operation Range
24	4.0V to 5.5V	AT89S51-24AC AT89S51-24JC AT89S51-24PC AT89S51-24SC	44A 44J 40P6 42PS6	Commercial (0° C to 70° C)
		AT89S51-24AI AT89S51-24JI AT89S51-24PI AT89S51-24SI	44A 44J 40P6 42PS6	Industrial (-40° C to 85° C)
33	4.5V to 5.5V	AT89S51-33AC AT89S51-33JC AT89S51-33PC AT89S51-33SC	44A 44J 40P6 42PS6	Commercial (0° C to 70° C)

	Package Type
A	44-lead, Thin Plastic Gull Wing Quad Flatpack (TQFP)
J	44-lead, Plastic J-leaded Chip Carrier (PLCC)
P6	40-pin, 0.600" Wide, Plastic Dual Inline Package (PDIP)
PS6	42-pin, 0.600" Wide, Plastic Dual Inline Package (PDIP)

ckaging Information

A – TQFP



COMMON DIMENSIONS
(Unit of Measure = mm)

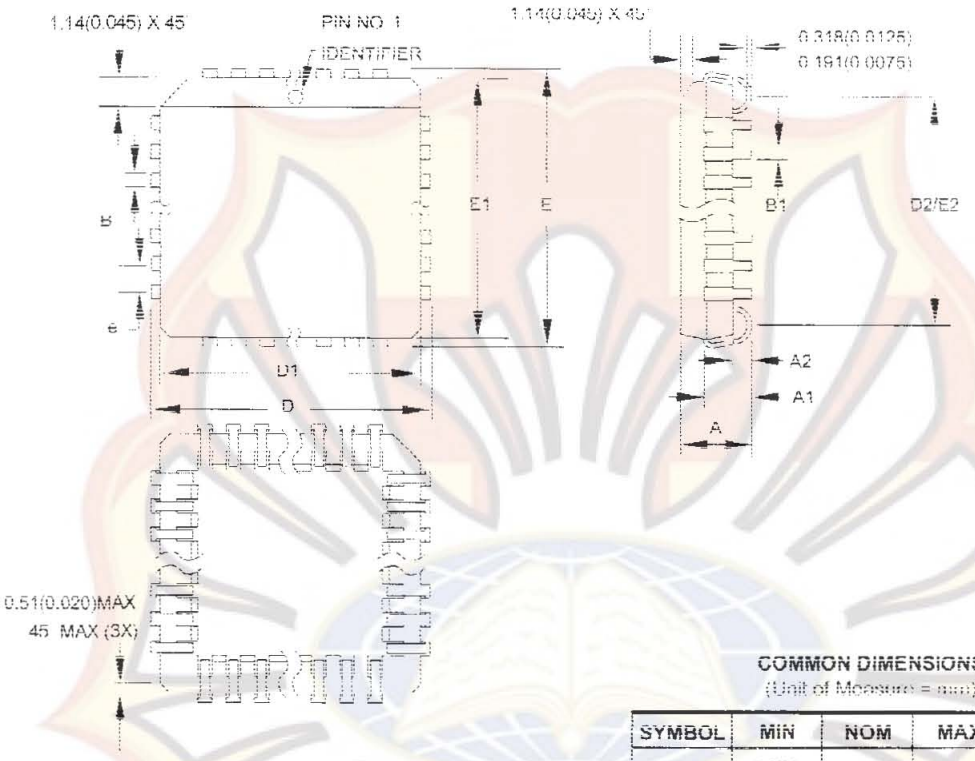
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05		0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
E	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
B	0.30	–	0.45	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.80 TYP			

Notes:
1. This package conforms to JEDEC reference MS-026, Variation ACB.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10 mm maximum.

10/5/2001

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44A**, 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	44A	B

– PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

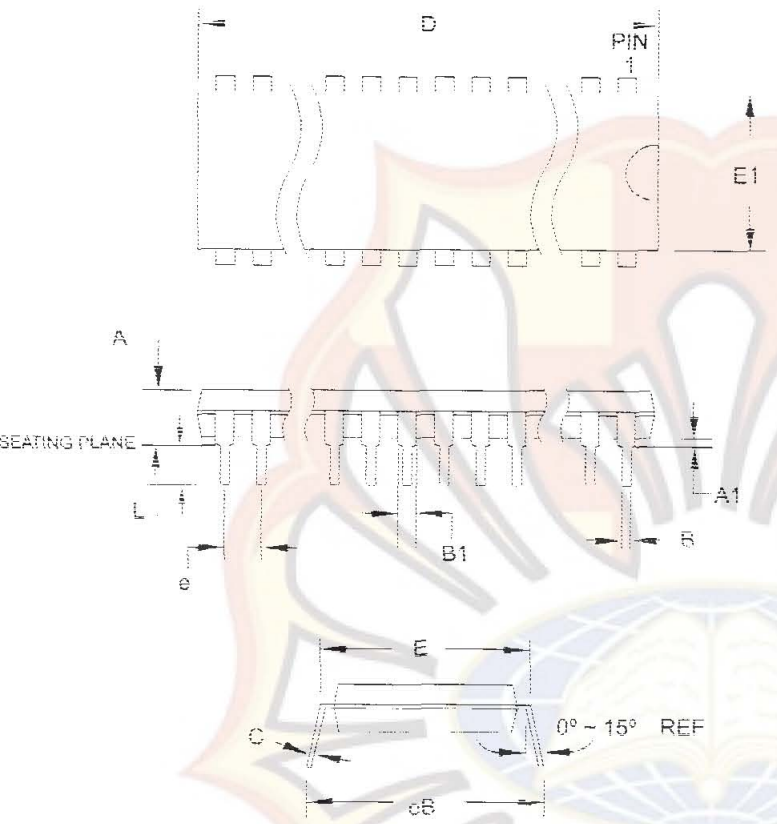
SYMBOL	MIN	NOM	MAX	NOTE
A	4.191		4.572	
A1	2.286	–	3.048	
A2	0.508	–	–	
D	17.399	–	17.653	
D1	16.510	–	16.662	Note 2
E	17.399	–	17.653	
E1	16.510	–	16.662	Note 2
D2/E2	14.986	–	16.002	
B	0.660	–	0.813	
B1	0.330		0.533	
e	1.270 TYP			

Notes:
1. This package conforms to JEDEC reference MS-018, Variation AC.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44J**, 44-lead, Plastic J-leaded Chip Carrier (PLCC)	44J	B

P6 – PDIP



COMMON DIMENSIONS
(Unit of Measure = mm)

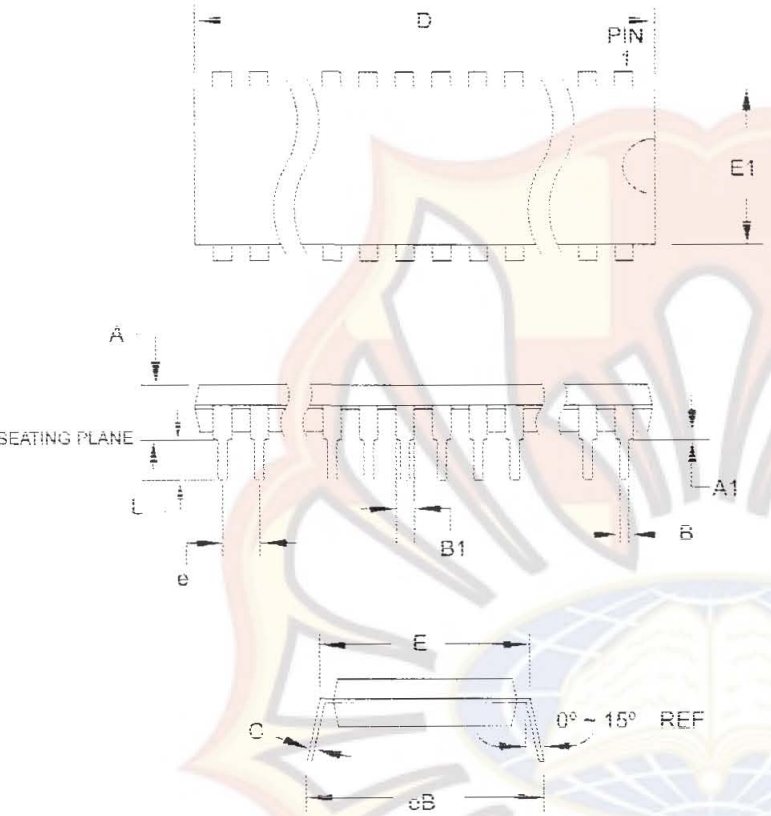
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	4.826	
A1	0.381	–	–	
D	52.070	–	52.578	Note 2
E	15.240	–	15.875	
E1	13.462	–	13.970	Note 2
B	0.356	–	0.559	
B1	1.041	–	1.651	
L	3.048	–	3.556	
C	0.203	–	0.381	
eB	15.494	–	17.526	
e	2.540 TYP			

Notes:
1. This package conforms to JEDEC reference MS-011, Variation AC.
2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

09/28/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**40P6**, 40-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)	40P6	B

S6 – PDIP



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	4.83	
A1	0.51			
D	36.70	–	36.96	Note 2
E	15.24	–	15.88	
E1	13.46		13.97	Note 2
B	0.38	–	0.50	
B1	0.76	–	1.27	
L	3.05	–	3.43	
C	0.20	–	0.30	
eB	–	–	18.55	
e	1.78 TYP			

Notes:
1. This package conforms to JEDEC reference MS-011, Variation AC.
2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

11/6/03

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**42PS6**, 42-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)	42PS6	A

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BP 123
38521 Saint-Egreve Cedex, France
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Fax: (33) 4-76-58-34-80

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2487B–MICRO–12/03

FAIRCHILD
SEMICONDUCTOR

BD135/137/139

Medium Power Linear and Switching Applications

- Complement to BD136, BD138 and BD140 respectively

1. Emitter 2.Collector 3.Base

NPN Epitaxial Silicon Transistor

Absolute Maximum Ratings T_C=25°C unless otherwise noted

Symbol	Parameter		Value	Units
V_{CBO}	Collector-Base Voltage	: BD135	45	V
		: BD137	60	V
		: BD139	80	V
V_{CEO}	Collector-Emitter Voltage	: BD135	45	V
		: BD137	60	V
		: BD139	80	V
V_{EBO}	Emitter-Base Voltage		5	V
I_C	Collector Current (DC)		1.5	A
I_{CP}	Collector Current (Pulse)		3.0	A
I_B	Base Current		0.5	A
P_C	Collector Dissipation (T_C=25°C)		12.5	W
P_C	Collector Dissipation (T_a=25°C)		1.25	W
T_J	Junction Temperature		150	°C
T_{STG}	Storage Temperature		- 55 ~ 150	°C

Electrical Characteristics T_C 25°C unless otherwise noted

Symbol	Parameter		Test Condition	Min.	Typ.	Max.	Units
V_{CEO}(sus)	Collector-Emitter Sustaining Voltage						
		: BD135	I_C = 30mA, I_B = 0	45			V
		BD137		60			V
		BD139		80			V
I_{CBO}	Collector Cut-off Current		V_{CB} = 30V, I_E = 0			0.1	μA
I_{EBO}	Emitter Cut-off Current		V_{EB} = 5V, I_C = 0			10	μA
h_{FE1}	DC Current Gain	: ALL DEVICE	V_{CE} = 2V, I_C = 5mA	25			
h_{FE2}		: ALL DEVICE	V_{CE} = 2V, I_C = 0.5A	25			
h_{FE3}		: BD135	V_{CE} = 2V, I_C = 150mA	40		250	
		BD137, BD139		40		160	
V_{CE}(sat)	Collector-Emitter Saturation Voltage		I_C = 500mA, I_B = 50mA			0.5	V
V_{BE}(on)	Base-Emitter ON Voltage		V_{CE} = 2V, I_C = 0.5A			1	V

h_{FE} Classification

Classification	6	10	16
h_{FE3}	40 ~ 100	63 ~ 160	100 ~ 250

Typical Characteristics

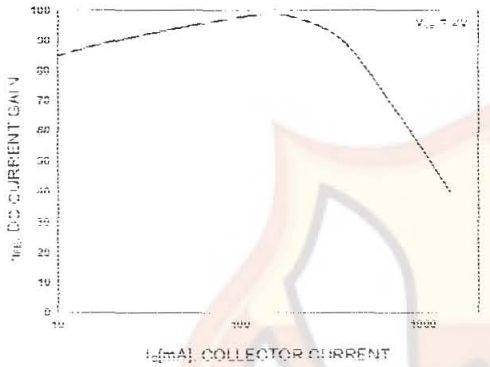


Figure 1. DC current Gain

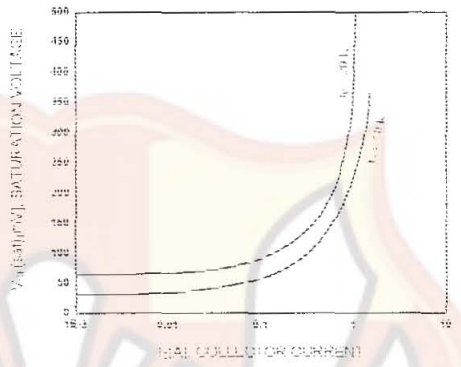


Figure 2. Collector-Emitter Saturation Voltage

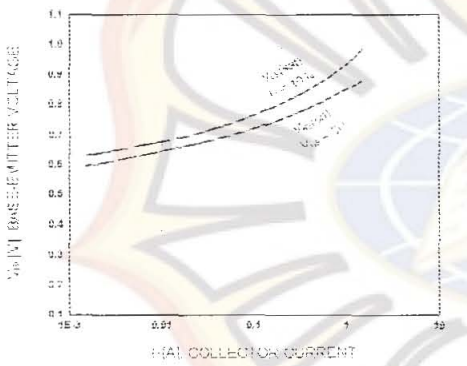


Figure 3. Base-Emitter Voltage

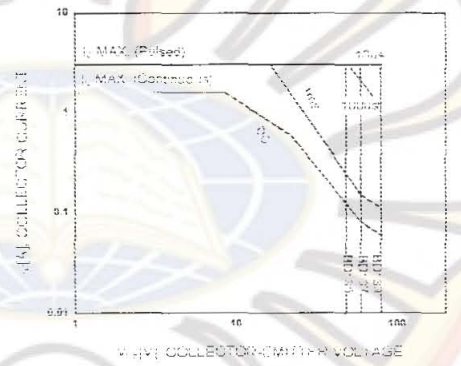


Figure 4. Safe Operating Area

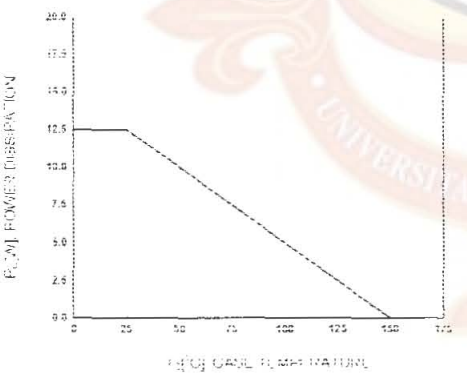
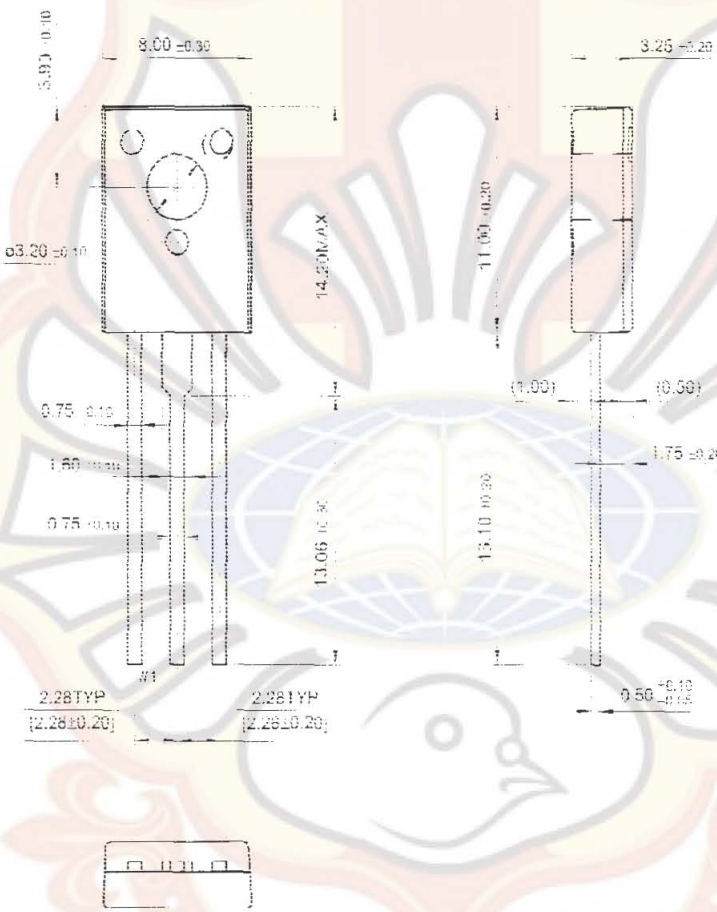


Figure 5. Power Derating

Package Demensions

TO-126



Dimensions in Millimeters

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CROSSVOLT™	POP™	UHC™
E^2CMOS™	PowerTrench®	VCX™
FACT™	QFET™	
FACT Quiet Series™	QS™	
FAST®	Quiet Series™	
FASTr™	SuperSOT™-3	
GTO™	SuperSOT™-6	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	*Product Status*	*Definition*
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

MOTOROLA

SCHMITT TRIGGERS
DUAL GATE/HEX INVERTER

SN54/74LS13
SN54/74LS14

SCHMITT TRIGGERS
DUAL GATE/HEX INVERTER

LOW POWER SCHOTTKY

The SN54LS/74LS13 and SN54LS/74LS14 contain logic gates/inverters which accept standard TTL input signals and provide standard TTL output levels. They are capable of transforming slowly changing input signals into sharply defined, jitter-free output signals. Additionally, they have greater noise margin than conventional inverters.

Each circuit contains a Schmitt trigger followed by a Darlington level shifter and a phase splitter driving a TTL totem pole output. The Schmitt trigger uses positive feedback to effectively speed-up slow input transitions, and provide different input threshold voltages for positive and negative-going transitions. This hysteresis between the positive-going and negative-going input thresholds (typically 800 mV) is determined internally by resistor ratios and is essentially insensitive to temperature and supply voltage variations.

J SUFFIX
CERAMIC
CASE 632-08

N SUFFIX
PLASTIC
CASE 646-06

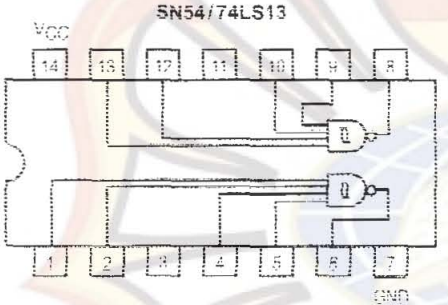
D SUFFIX
SOIC
CASE 751A-02

ORDERING INFORMATION

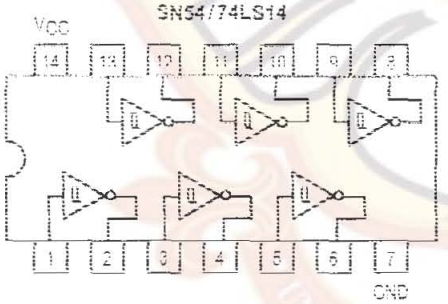
SN54LSXXJ	Ceramic
SN74LSXXN	Plastic
SN74LSXXD	SOIC

LOGIC AND CONNECTION DIAGRAMS

SN54/74LS13



SN54/74LS14



GUARANTEED OPERATING RANGES

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	54 74	4.5 4.75	5.0 5.0	5.5 5.25	V
T_A	Operating Ambient Temperature Range	54 74	−55 0	25 25	125 70	C
I_{OH}	Output Current — High	54, 74			0.4	mA
I_{OL}	Output Current — Low	54 74			4.0 8.0	mA

C CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter		Limits Min	Typ	Max	Unit	Test Conditions
V_{T+}	Positive-Going Threshold Voltage		1.5		2.0	V	V_{CC} = 5.0 V
V_{T-}	Negative-Going Threshold Voltage		0.6		1.1	V	V_{CC} = 5.0 V
$V_{T+}-V_{T-}$	Hysteresis		0.4	0.8		V	V_{CC} = 5.0 V
V_{IK}	Input Clamp Diode Voltage			−0.65	−1.5	V	V_{CC} = MIN, I_{IN} = −18 mA
V_{OH}	Output HIGH Voltage	54	2.5	3.4		V	V_{CC} = MIN, I_{OH} = −400 µA, V_{IN} = V_{IL}
		74	2.7	3.4		V	
V_{OL}	Output LOW Voltage	54, 74		0.25	0.4	V	V_{CC} = MIN, I_{OL} = 4.0 mA, V_{IN} = 2.0 V
		74		0.35	0.5	V	V_{CC} = MIN, I_{OL} = 8.0 mA, V_{IN} = 2.0 V
I_{T+}	Input Current at Positive-Going Threshold			−0.14		mA	V_{CC} = 5.0 V, V_{IN} = V_{T+}
I_{T-}	Input Current at Negative-Going Threshold			−0.18		mA	V_{CC} = 5.0 V, V_{IN} = V_{T-}
I_{IH}	Input HIGH Current			1.0	20	µA	V_{CC} = MAX, V_{IN} = 2.7 V
					0.1	mA	V_{CC} = MAX, V_{IN} = 7.0 V
I_{IL}	Input LOW Current				−0.4	mA	V_{CC} = MAX, V_{IN} = 0.4 V
I_{OS}	Short Circuit Current (Note 1)		−20		−100	mA	V_{CC} = MAX, V_{OUT} = 0 V
I_{CC}	Power Supply Current Total, Output HIGH	LS13		2.9	6.0	mA	V_{CC} = MAX
		LS14		5.6	10		
	Total, Output LOW	LS13		4.1	7.0		
		LS14		12	21		

Note 1: Not more than one output should be shorted at a time, nor for more than 1 second.

C CHARACTERISTICS (T_A = 25°C)

Symbol	Parameter	Max LS13	Max LS14	Unit	Test Conditions
t_{PLH}	Propagation Delay, Input to Output	22	22	ns	V_{CC} = 5.0 V
t_{PHL}	Propagation Delay, Input to Output	27	22	ns	C_L = 15 pF

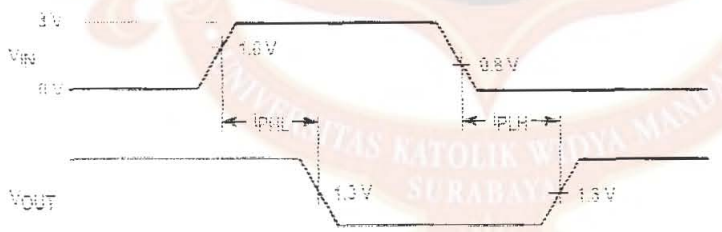


Figure 1. AC Waveforms

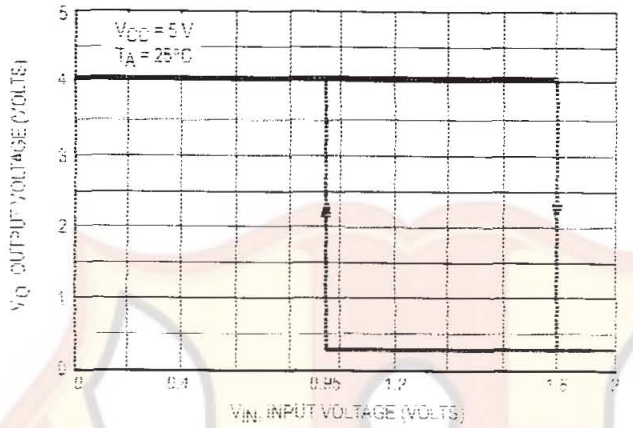


Figure 2. V_{IN} versus V_{OUT} Transfer Function

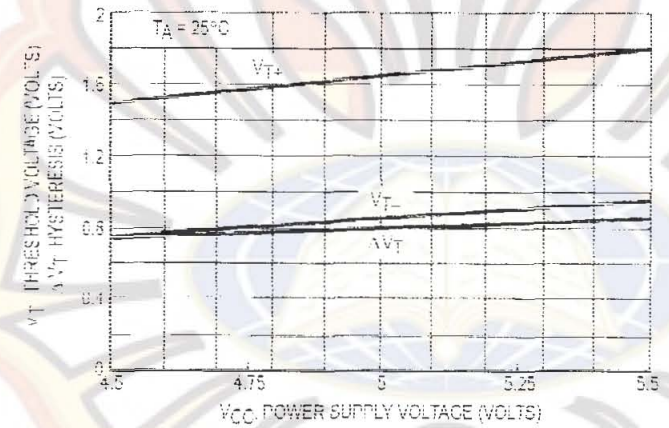


Figure 3. Threshold Voltage and Hysteresis versus Power Supply Voltage

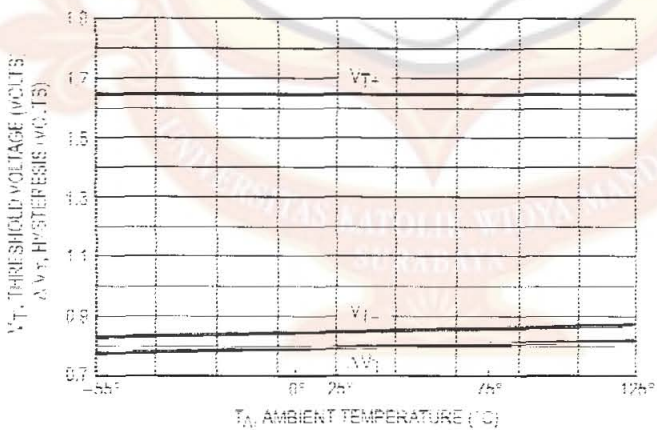


Figure 4. Threshold Voltage Hysteresis versus Temperature

National Semiconductor

February 1995

LM78XX Series Voltage Regulators

General Description

The LM78XX series of three terminal regulators is available with several fixed output voltages making them useful in a wide range of applications. One of these is local on card regulation, eliminating the distribution problems associated with single point regulation. The voltages available allow these regulators to be used in logic systems, instrumentation, HiFi, and other solid state electronic equipment. Although designed primarily as fixed voltage regulators these devices can be used with external components to obtain adjustable voltages and currents.

The LM78XX series is available in an aluminum TO-3 package which will allow over 1.0A load current if adequate heat sinking is provided. Current limiting is included to limit the peak output current to a safe value. Safe area protection for the output transistor is provided to limit internal power dissipation. If internal power dissipation becomes too high for the heat sinking provided, the thermal shutdown circuit takes over preventing the IC from overheating.

Considerable effort was expanded to make the LM78XX series of regulators easy to use and minimize the number of external components. It is not necessary to bypass the output, although this does improve transient response. Input bypassing is needed only if the regulator is located far from the filter capacitor of the power supply.

For output voltage other than 5V, 12V and 15V the LM117 series provides an output voltage range from 1.2V to 57V.

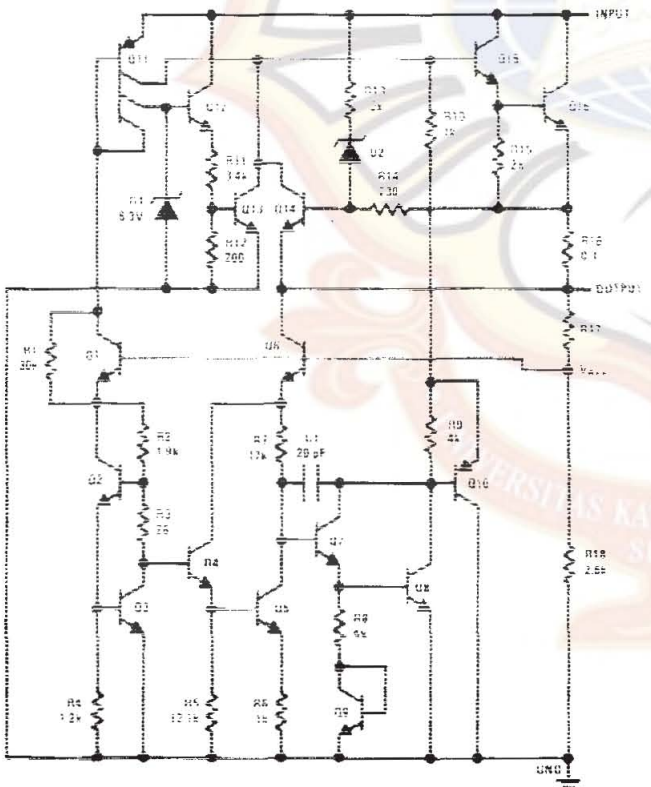
Features

- Output current in excess of 1A
- Internal thermal overload protection
- No external components required
- Output transistor safe area protection
- Internal short circuit current limit
- Available in the aluminum TO-3 package

Voltage Range

LM7805C	5V
LM7812C	12V
LM7815C	15V

Schematic and Connection Diagrams



TL/H/7746–1

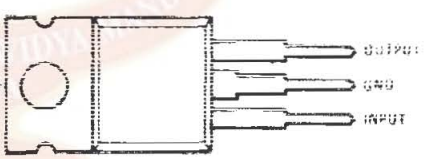
Metal Can Package
TO-3 (K)
Aluminum

TL/H/7746–2

Bottom View

Order Number LM7805CK, LM7812CK or LM7815CK
See NS Package Number KC02A

Plastic Package
TO-220 (T)



TL/H/7746–3

Top View

Order Number LM7805CT, LM7812CT or LM7815CT
See NS Package Number T03B

Absolute Maximum Ratings

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Input Voltage (V_O = 5V, 12V and 15V)	35V
Internal Power Dissipation (Note 1)	Internally Limited
Operating Temperature Range (T_A)	0°C to +70°C
Maximum Junction Temperature (K Package)	150°C
(T Package)	150°C
Storage Temperature Range	−65°C to +150°C
Lead Temperature (Soldering, 10 sec.)	
TO-3 Package K	300°C
TO-220 Package T	230°C

Electrical Characteristics LM78XXC (Note 2) 0°C ≤ T_j ≤ 125°C unless otherwise noted.

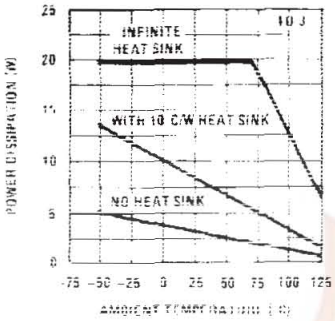
Output Voltage				5V			12V			15V			
Input Voltage (unless otherwise noted)				10V			19V			23V			Units
Symbol	Parameter	Conditions		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_O	Output Voltage	T_j = 25°C, 5 mA ≤ I_O ≤ 1A		4.8	5	5.2	11.5	12	12.5	14.4	15	15.6	V
		P_D ≤ 15W, 5 mA ≤ I_O ≤ 1A		4.75		5.25	11.4		12.6	14.25		15.75	V
		V_{MIN} ≤ V_{IN} ≤ V_{MAX}		(7.5 ≤ V_{IN} ≤ 20)			(14.5 ≤ V_{IN} ≤ 27)			(17.5 ≤ V_{IN} ≤ 30)			V
ΔV_O	Line Regulation	I_O = 500 mA	T_j = 25°C		3	50		4	120		4	120	mV
			ΔV_{IN}	(7 ≤ V_{IN} ≤ 25)			(14.5 ≤ V_{IN} ≤ 30)			(17.6 ≤ V_{IN} ≤ 30)			V
			0°C ≤ T_j ≤ +125°C			50			120			150	mV
			ΔV_{IN}	(8 ≤ V_{IN} ≤ 20)			(15 ≤ V_{IN} ≤ 27)			(18.5 ≤ V_{IN} ≤ 30)			V
		I_O ≤ 1A	T_j = 25°C			50			120			150	mV
			ΔV_{IN}	(7.5 ≤ V_{IN} ≤ 20)			(14.6 ≤ V_{IN} ≤ 27)			(17.7 ≤ V_{IN} ≤ 30)			V
			0°C ≤ T_j ≤ +125°C			25			60			75	mV
			ΔV_{IN}	(8 ≤ V_{IN} ≤ 12)			(15 ≤ V_{IN} ≤ 22)			(20 ≤ V_{IN} ≤ 26)			V
ΔV_O	Load Regulation	T_j = 25°C	5 mA ≤ I_O ≤ 1.5A		10	50		12	120		12	150	mV
			250 mA ≤ I_O ≤ 750 mA			25			60			75	mV
		5 mA ≤ I_O ≤ 1A, 0°C ≤ T_j ≤ +125°C				50			120			150	mV
I_Q	Quiescent Current	I_O ≤ 1A	T_j = 25°C			8			8			8	mA
			0°C ≤ T_j ≤ +125°C			8.5			8.5			8.5	mA
ΔI_Q	Quiescent Current Change	5 mA ≤ I_O ≤ 1A				0.5			0.5			0.5	mA
		T_j = 25°C, I_O ≤ 1A				1.0			1.0			1.0	mA
		V_{MIN} ≤ V_{IN} ≤ V_{MAX}		(7.5 ≤ V_{IN} ≤ 20)			(14.6 ≤ V_{IN} ≤ 27)			(17.9 ≤ V_{IN} ≤ 30)			V
		I_O ≤ 500 mA, 0°C ≤ T_j ≤ +125°C				1.0			1.0			1.0	mA
		V_{MIN} ≤ V_{IN} ≤ V_{MAX}		(7 ≤ V_{IN} ≤ 25)			(14.6 ≤ V_{IN} ≤ 30)			(17.6 ≤ V_{IN} ≤ 30)			V
V_N	Output Noise Voltage	T_A = 25°C, 10 Hz ≤ f ≤ 100 kHz			40			75			90		μV
$\frac{\Delta V_{IN}}{\Delta V_{OUT}}$	Ripple Rejection	f = 120 Hz	I_O ≤ 1A, T_j = 25°C or I_O ≤ 500 mA, 0°C ≤ T_j ≤ +125°C	62	80		55	72		54	70		dB
				62			55			54			dB
		V_{MIN} ≤ V_{IN} ≤ V_{MAX}		(8 ≤ V_{IN} ≤ 18)			(15 ≤ V_{IN} ≤ 25)			(18.5 ≤ V_{IN} ≤ 28.5)			V
R_O	Dropout Voltage	T_j = 25°C, I_{OUT} = 1A			2.0			2.0			2.0		V
	Output Resistance	f = 1 kHz			8			18			19		mΩ
	Short Circuit Current	T_j = 25°C			2.1			1.5			1.2		A
	Peak Output Current	T_j = 25°C			2.4			2.4			2.4		A
	Average TC of V_{OUT}	0°C ≤ T_j ≤ +125°C, I_O = 5 mA			0.6			1.5			1.8		mV/°C
V_{IN}	Input Voltage Required to Maintain Line Regulation	T_j = 25°C, I_O = 1A			7.5		14.6			17.7			V

Note 1: Thermal resistance of the TO-3 package (K, KC) is typically 4°C/W junction to case and 35°C/W case to ambient. Thermal resistance of the TO-220 package (T) is typically 4°C/W junction to case and 50°C/W case to ambient.

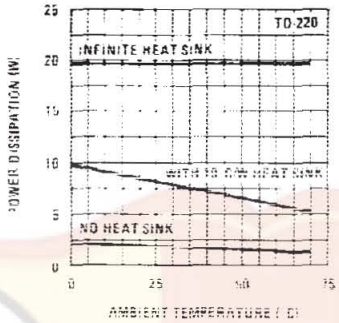
Note 2: All characteristics are measured with capacitor across the input of 0.22 μF, and a capacitor across the output of 0.1μF. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t_w = 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.

Typical Performance Characteristics

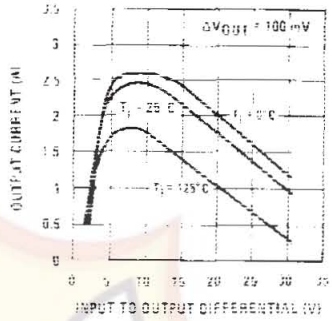
Maximum Average Power Dissipation



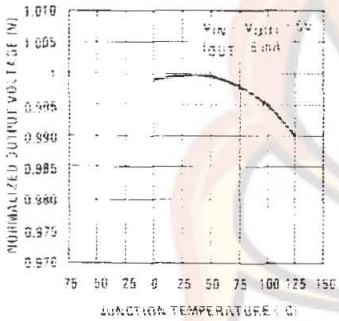
Maximum Average Power Dissipation



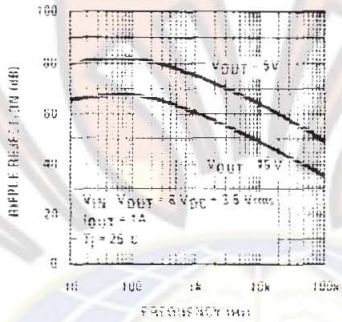
Peak Output Current



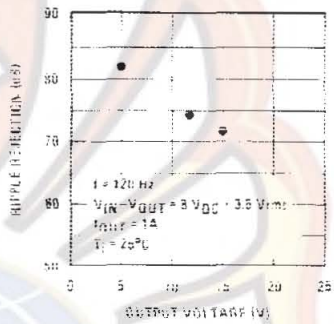
Output Voltage (Normalized to 1V at T_J = 25°C)



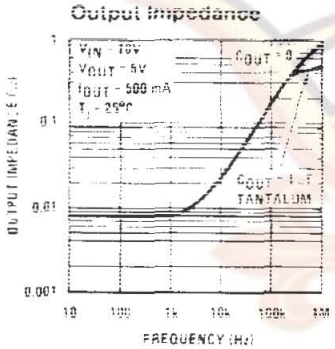
Ripple Rejection



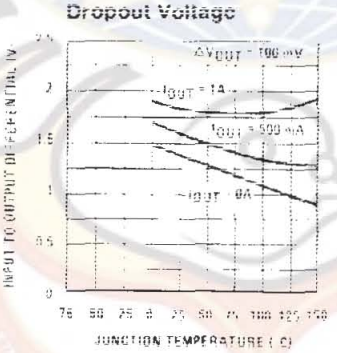
Ripple Rejection



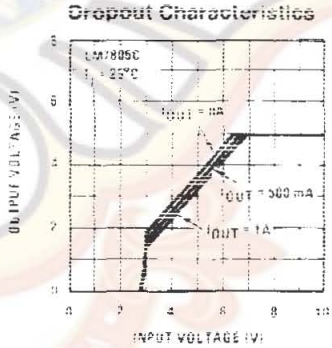
Output Impedance



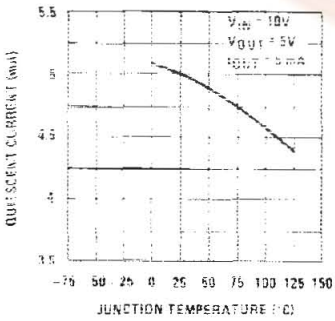
Dropout Voltage



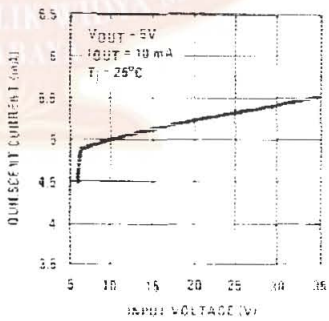
Dropout Characteristics



Quiescent Current



Quiescent Current



TL/H/7746–4

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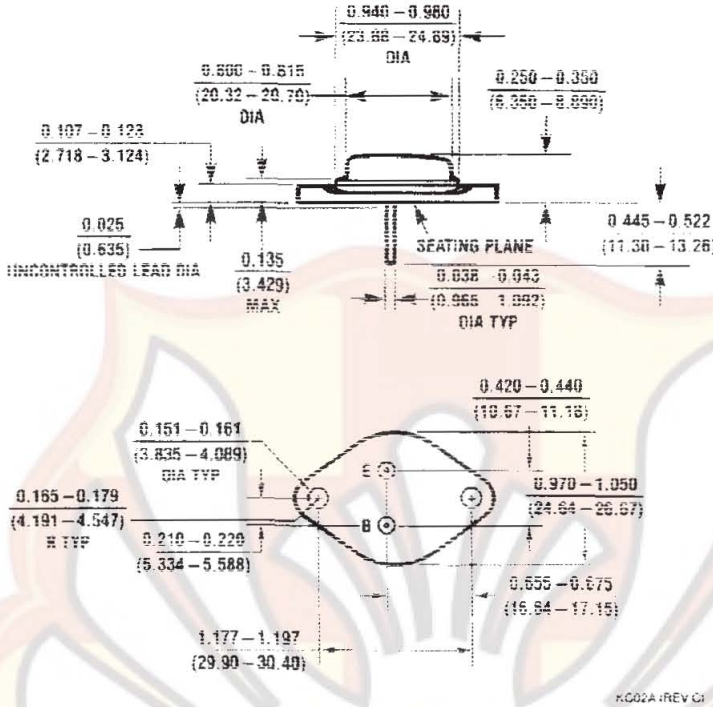
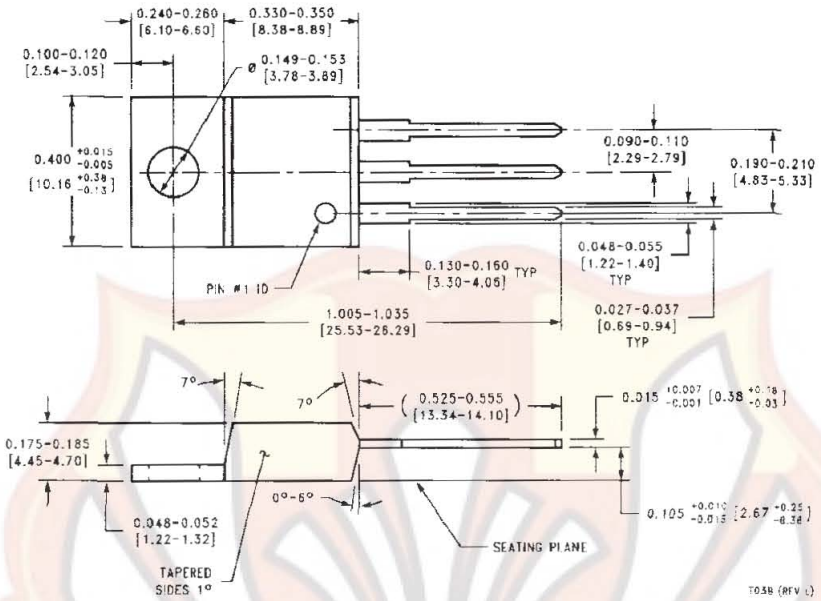
SURABAYA

Physical Dimensions inches (millimeters)



Aluminum Metal Can Package (KC)
Order Number LM7805CK, LM7812CK or LM7815CK
NS Package Number KC02A

Physical Dimensions inches (millimeters) (Continued)



TO-220 Package (T)
Order Number LM7805CT, LM7812CT or LM7815CT
NS Package Number T03B

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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